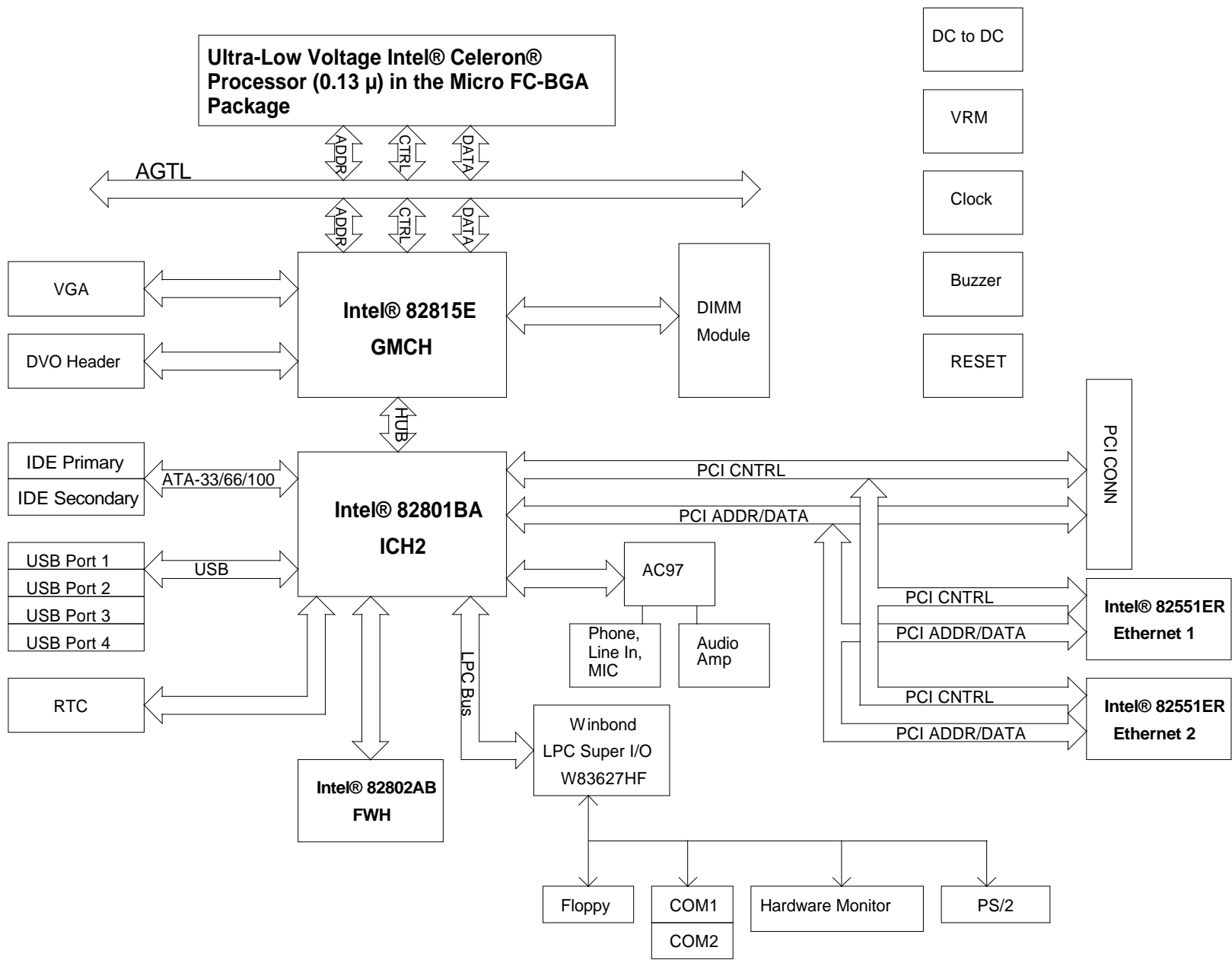


Intel® 815E Interactive Client Reference Design
Block Diagram



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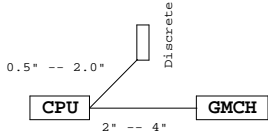
MANUFACTURING OPTIONS (Opt = XX):
CA = Communications Appliance Only
IC = Interactive Client Only

General Board Design Requirements

- >> Board material shall be FR-4.
- >> Right angle traces shall not be used.
- >> Vias for decoupling capacitors shall be kept as close as possible to the capacitor pad.
- >> Trace impedance shall be 60 ohms, +/- 15%
- >> Total board thickness shall be .062".
- >> GND layers shall not be split.
- >> Top and bottom (outer) layers shall be no less than 1/2 oz copper before plating, inner layers shall be 1 oz copper.
- >> Series terminating resistors shall be kept as close to the driving pin as possible.
- >> Daisy chain signals going to more than one point shall not use stubs.
- >> Unless otherwise noted, all signal traces shall be between 5 and 6 mil width.
- >> Unless otherwise noted, minimum space between traces shall be 10 mils, including adjacent layers.
- >> One registration target shall be included on each corner of the board.
- >> Other specific routing requirements are included throughout schematic sheets.

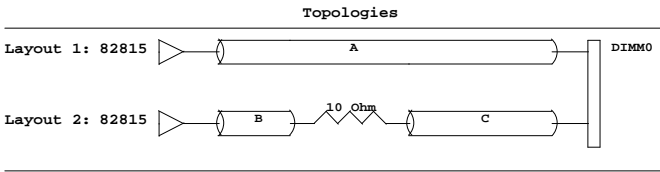
CPU Routing Requirements

- >> Route all GTL traces between CPU and GMCH as shown in the diagram to the right.
- >> Route all traces between CPU and GMCH on a layer adjacent to a ground plane, without layer changes.
- >> Minimum space between traces shall be 10 mils (unless otherwise noted); this includes adjacent signal layers.
- >> Minimum space between traces may be reduced to 5 mils when breaking out of a footprint. The total length of trace routed using 5 mil spacing shall be less than 250 mils.
- >> The following signals require 25 mil spacing from other traces, including adjacent layers:
 - HA#[31:3], HD#[63:0], BREQ#0, HADS#, BNR#, BPRI#, HLOCK#, DEFER#, HTRDY#, DBSY#, DRDY#, HIT#, HITM#, A20M#, IGNNE#, INIT#, INTR, NMI, PWR_OK_2P5, SMI#, CPUSLP#, STPCLK#, 66#/100SEL,100#/133SEL,FERR#,CPURST#, HREQ#[4:0], RS#[2:0], GTLREF[7:0], PLL[2:1], (CPU_TCK/TMS/TDI/TDO/TRST#, PRDY#, PREQ#).
- >> ACTL signals shall be well isolated from system memory signals. ACTL signal trace edges shall be at least 30 mils from system memory trace edges within 100 mils of the ball of the 82815 GMCH.
- >> Route GTLREF using 25 mil minimum width trace, and separate from all other traces by 25 mils minimum.
- >> Route PLL[2:1] using 25 mil minimum width trace, minimize loop area, and separate from all other traces by 25 mils minimum.



Memory Bus Routing Requirements

- >> Minimum space between memory traces and other types of traces is 30 mils, including adjacent signal layers.
- >> Memory address, data, and control lines shall be routed as separate groups and treated as different signal types.

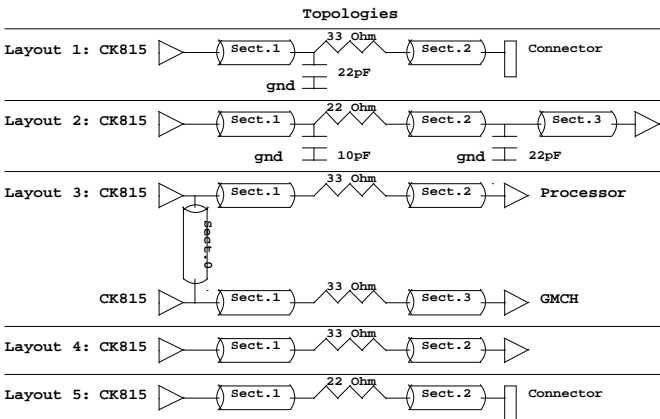


Routing Solution :

Signal	Topologies	Width (mils)	Spacing (mils)	A (inches)	P (inches)	C (inches)
SM_CSA#[1..0]	Layout 1	5	10	1-4.5		
SM_MAA[7:4]	Layout 2	10	10		0.4-0.5	2-4
SM_CKE[1:0]	Layout 1	10	10	3-4		
SM_MD[63:0]	Layout 1	5	10	1.75-4		
SM_DQMA[7:0]	Layout 1	10	10	1.5-3.5		
SM_CAS#, SM_RAS#, SM_WE#	Layout 1	10	10	1-4.0		
SM_BS[1:0], SM_MAA[12:8], [3:0]	Layout 1	10	10	1-4.0		

Clock Routing Requirements

- >> Clock traces shall not alternate layers.
- >> All clocks shall be routed 5 mils wide with 15 mil spacing to any other signals.
- >> It is recommended to place capacitor sites within 0.5 inches of the receiver of all clocks. They are useful in system debug and AC tuning.
- >> Series resistor for clock guidelines: 22 ohm for GMCH SCLK and SDRAM clocks. All other clocks use 33 ohm.
- >> Each DIMM clock shall be matched within ±10 mils.



Routing Solution :

Destination	Topologies	Sect.0	Sect.1	Sect.2	Sect.3
MEMCLK[3..0]	Layout 5	N/A	<0.5"	A	N/A
DCLK_WR	Layout 2	N/A	<0.5"=L1	A+3.5"-L1	0.5"
CPUHCLK	Layout 3	<0.1"	<0.5"	A+5.2"	N/A
GMCHHCLK			<0.5"		
GMCH_3V66	Layout 4	N/A	<0.5"	A+8"	N/A
ICH_3V66	Layout 4	N/A	<0.5"	A+8"	N/A
PCLKICH	Layout 4	N/A	<0.5"	A+8"	N/A
PCLK559A,B; PCLKFWH ; PCLKSIO	Layout 4	N/A	<0.5"	A+8.5" to A+14"	N/A
PCICLKA	Layout 1	N/A	<0.5"	A+5" to A+11"	N/A

PCI Bus Routing Requirements

PCI Bus GROUPS

- >> Address/Data Signals: AD[31:0]
- >> Control Signals:
 - C/BE[3:0]#, REQ[4:1]#, GNT[4:1]#, INT[A:D]#, PCIRST#, FRAME#, TRDY#, IRDY#, STOP#, DEVSEL#, SERR#, PERR#, PAR, LOCK#

Hub Interface Routing Requirements

- >> Hub interface data signals shall be routed with a trace width of 5 mils and a trace spacing of 20 mils. These signals may be routed with a trace width of 5 mils and a trace spacing of 15 mils for navigation around components or mounting holes. To break out of the GMCH and the ICH2, the hub interface data signals may be routed with a trace width of 5 mils and a trace spacing of 5 mils. The signals shall be separated to a trace width of 5 mils and a trace spacing of 20 mils, within 0.3 inch of the GMCH/ICH2 components.
- >> The maximum trace length for the hub interface data signals is 8 inches. These signals shall each be matched within 0.1 inch of the HLSTB and HLSTB# signals.
- >> HL[10:0] should be routed with a trace width of 5 mils and a trace spacing of 20 mils. These signals may be routed with a trace width of 5 mils and a trace spacing of 15 mils for navigation around components or mounting holes. The maximum trace length for the hub interface data signals is 7". These signals shall each be matched within .1" of the HLSTB and HLSTB# signals.

HUB Bus GROUPS

- >> Address/Data Signals: HL[10:0]
- >> Control Signals: HLSTB, HLSTB# (differential strobe pair).

DVO Interface Routing Requirements

- >> Route data signals (LTVDATA[11:0]) with a trace width of 5 mils and a trace spacing of 20 mils. These signals may be routed with a trace width of 5 mils and a trace spacing of 15 mils for navigation around components or mounting holes.
- >> To break out of the GMCH, the DVO data signals may be routed with a trace width of 5 mils and a trace spacing of 5 mils. The signals shall be separated to a trace width of 5 mils and a trace spacing of 20 mils, within 0.3 inch of the GMCH component. The maximum trace length for the DVO data signals is 7 inches. These signals shall each be matched within 0.1 inch of the LTVCLKOUT[1] and LTVCLKOUT[0] signals.
- >> Route the LTVCLKOUT[1:0] signals 5 mils wide and 20 mils apart. This signal pair shall be a minimum of 20 mils from any adjacent signals. The maximum length for LTVCLKOUT[1:0] is 7 inches and the two signals shall be the same length.

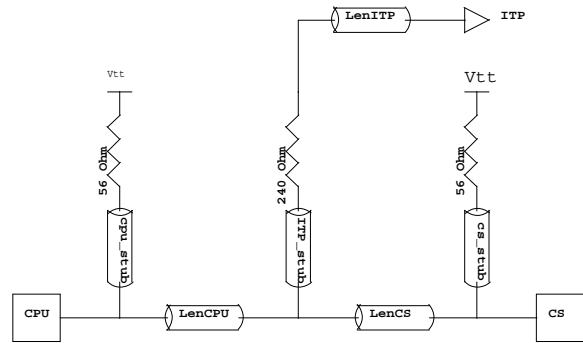
AC97 Interface Routing Requirements

- >> To ensure the maximum performance of the codec, proper component placement and routing techniques are required. These techniques include properly isolating the codec, associated audio circuitry, analog power supplies, and analog ground planes, from the rest of the motherboard. This includes plane splits and proper routing of signals not associated with the audio section. Contact your vendor for device-specific recommendations.
- >> Special consideration must be given for the ground return paths for the analog signals.
- >> Digital signals routed in the vicinity of the analog audio signals must not cross the power plane split lines. Analog and digital signals shall be located as far as possible from each other.
- >> Partition the board with all analog components grouped together in one area and all digital components in another.
- >> Separate analog and digital ground planes should be provided, with the digital components over the digital ground plane, and the analog components, including the analog power regulators, over the analog ground plane. The split between planes must be a minimum of 0.05 inches wide.
- >> Keep digital signal traces, especially the clocks, as far as possible from the analog input and voltage reference pins.
- >> Do not completely isolate the analog/audio ground plane from the rest of the board ground plane. There should be a single point (0.25 inches to 0.5 inches wide) where the analog/isolated ground plane connects to the main ground plane. The split between planes must be a minimum of 0.05 inches wide.
- >> Any signals entering or leaving the analog area must cross the ground split in the area where the analog ground is attached to the main motherboard ground. That is, no signal should cross the split/gap between the ground planes, which could cause a ground loop, thereby greatly increasing EMI issues and degrading the analog and digital signal quality.
- >> Bypassing and decoupling capacitors should be close to the IC pins, or positioned for the shortest connections to pins, with wide traces to reduce impedance.
- >> All resistors in the signal path or on the voltage reference should be metal film. Carbon resistors can be used for DC voltages and the power supply path, where the voltage coefficient, temperature coefficient, and noise are not factors.
- >> Regions between analog signal traces should be filled with copper, which should be electrically attached to the analog ground plane. Regions between digital signal traces should be filled with copper, which should be electrically attached to the digital ground plane.
- >> Locate the crystal or oscillator close to the codec.

Power Supply Routing Requirements

- >> All unrelated signals and power planes shall be kept away from the switching circuits, devices, magnetics, and traces.
- >> All traces associated with the input power/ground connectors, and the capacitors connected to these connectors, must be routed with minimum length and maximum width.
- >> Refer to the power supply data sheets and the schematic sheets for more detail.

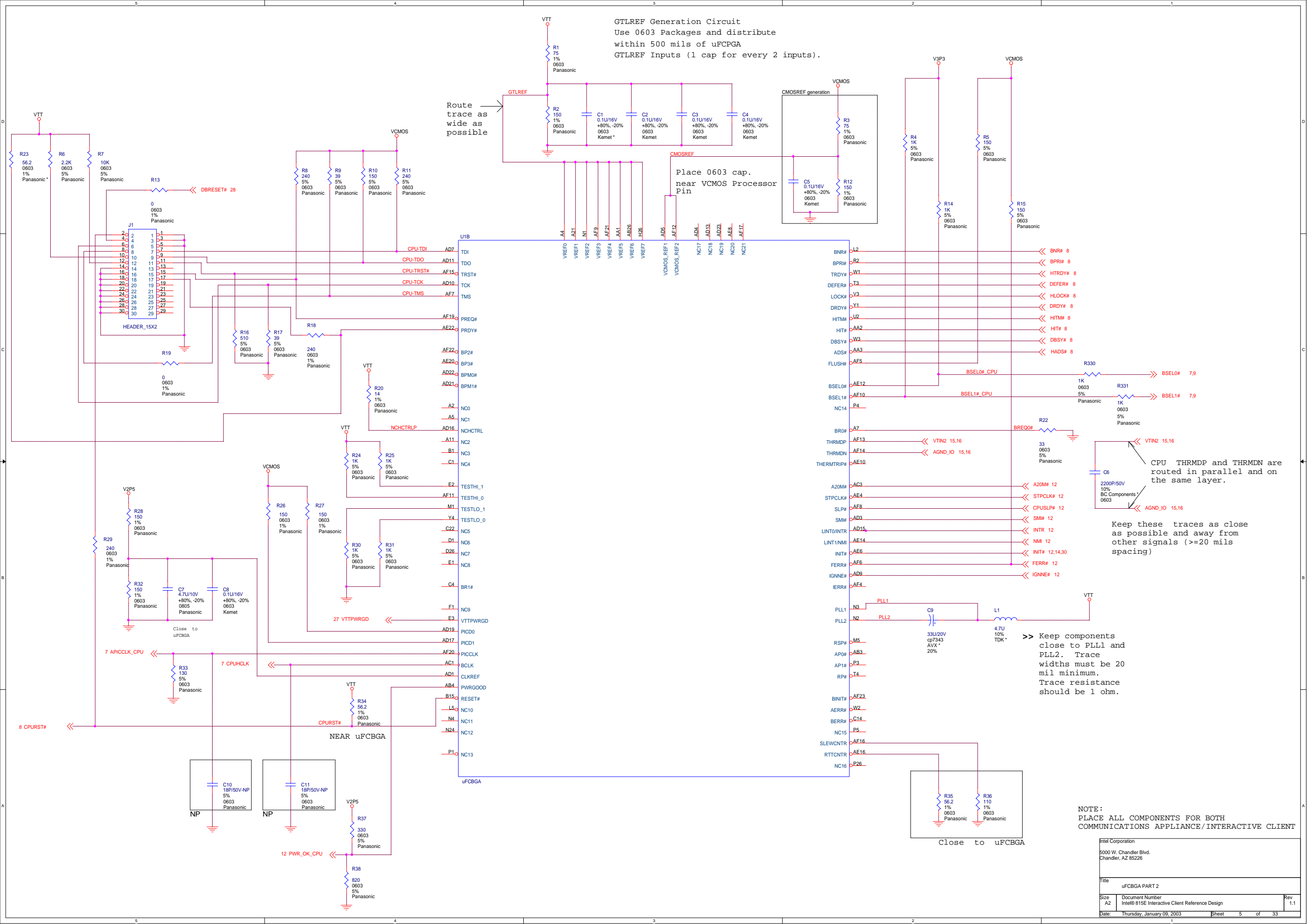
RESET#/RESET2# Routing Requirements

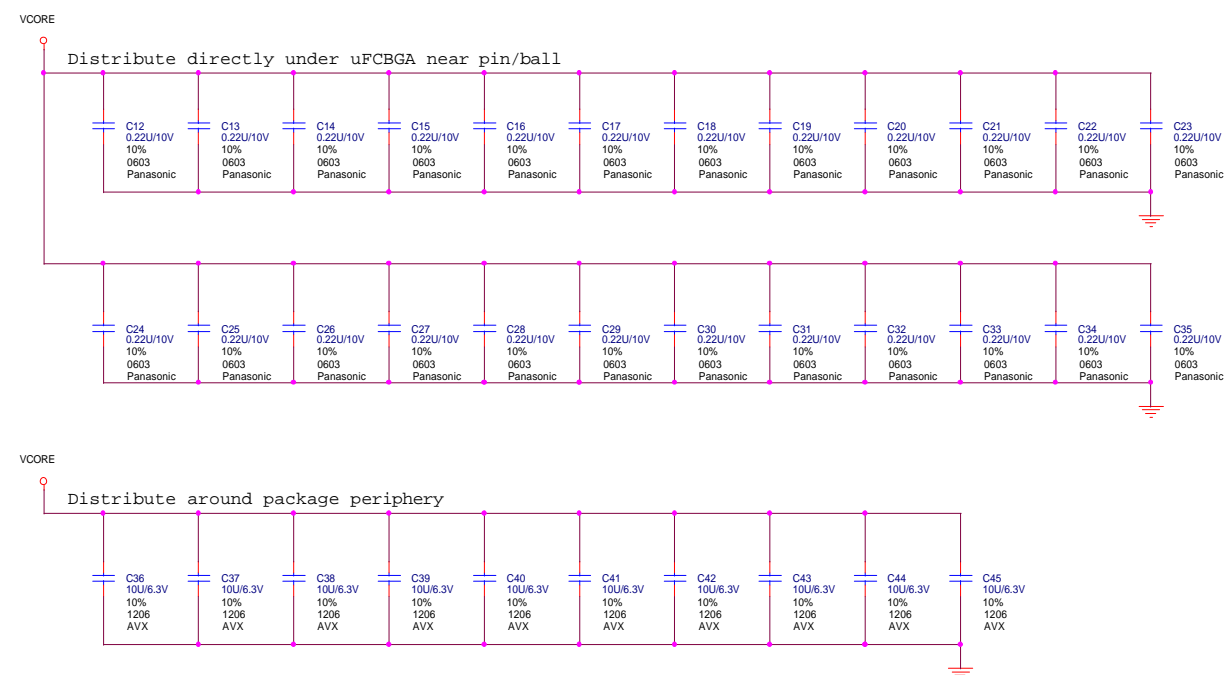
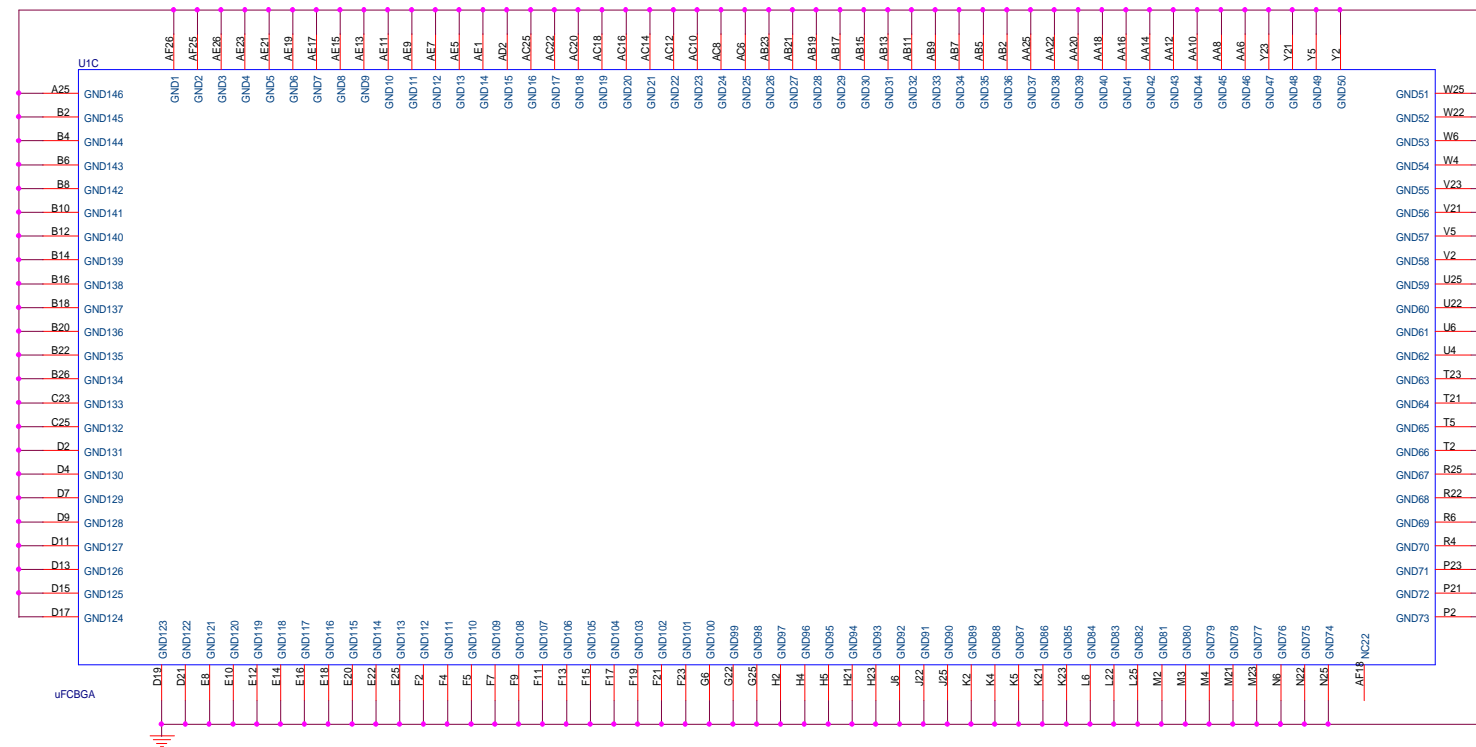


Routing Solution :

Parameter	Minimum (in)	Maximum (in)
LenCS	0.5	1.5
LenITP	1	3
LenCPU	0.5	1.5
cs stub	0.5	1
cpu stub	0.5	1
ITP stub	short as possible	

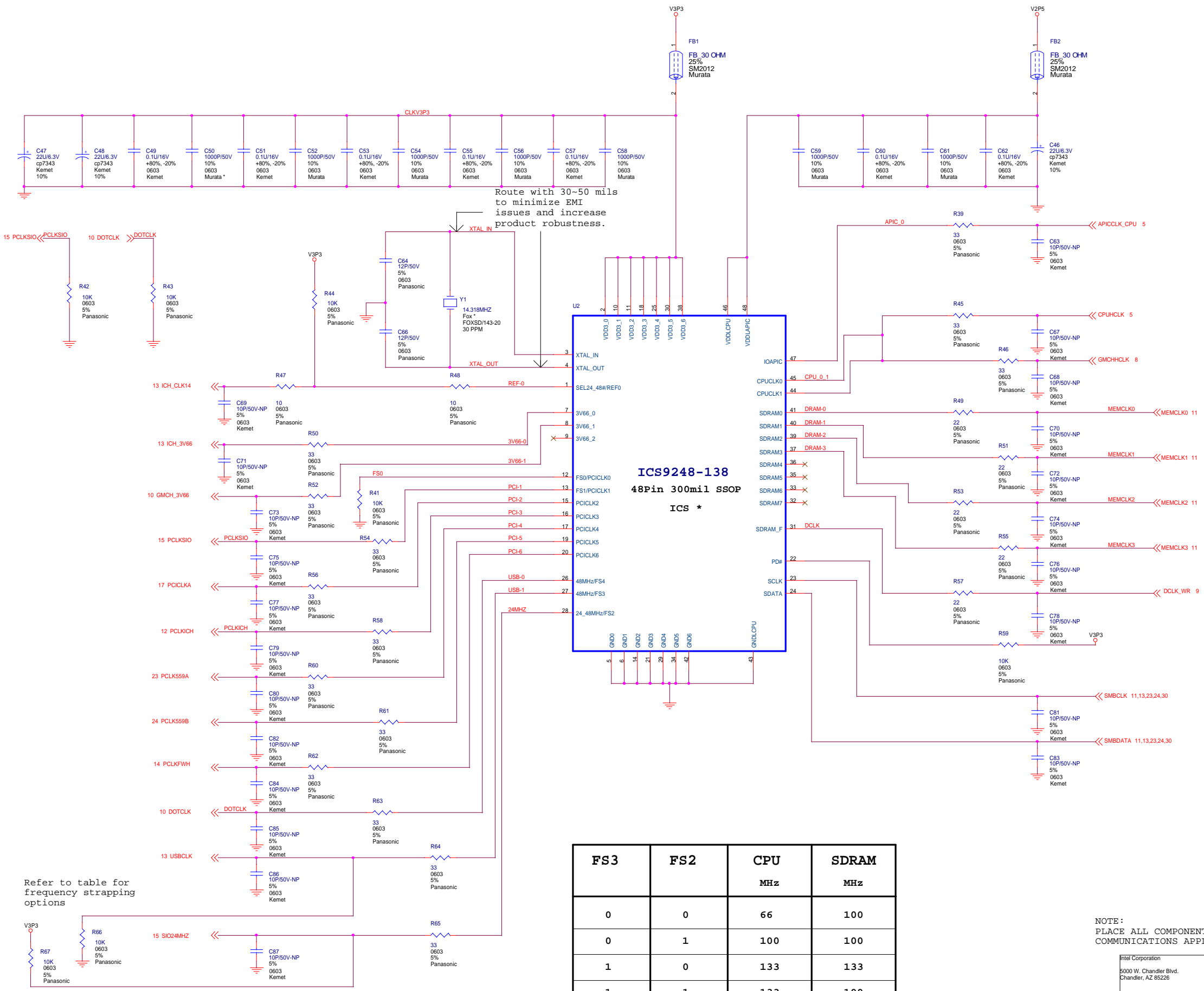






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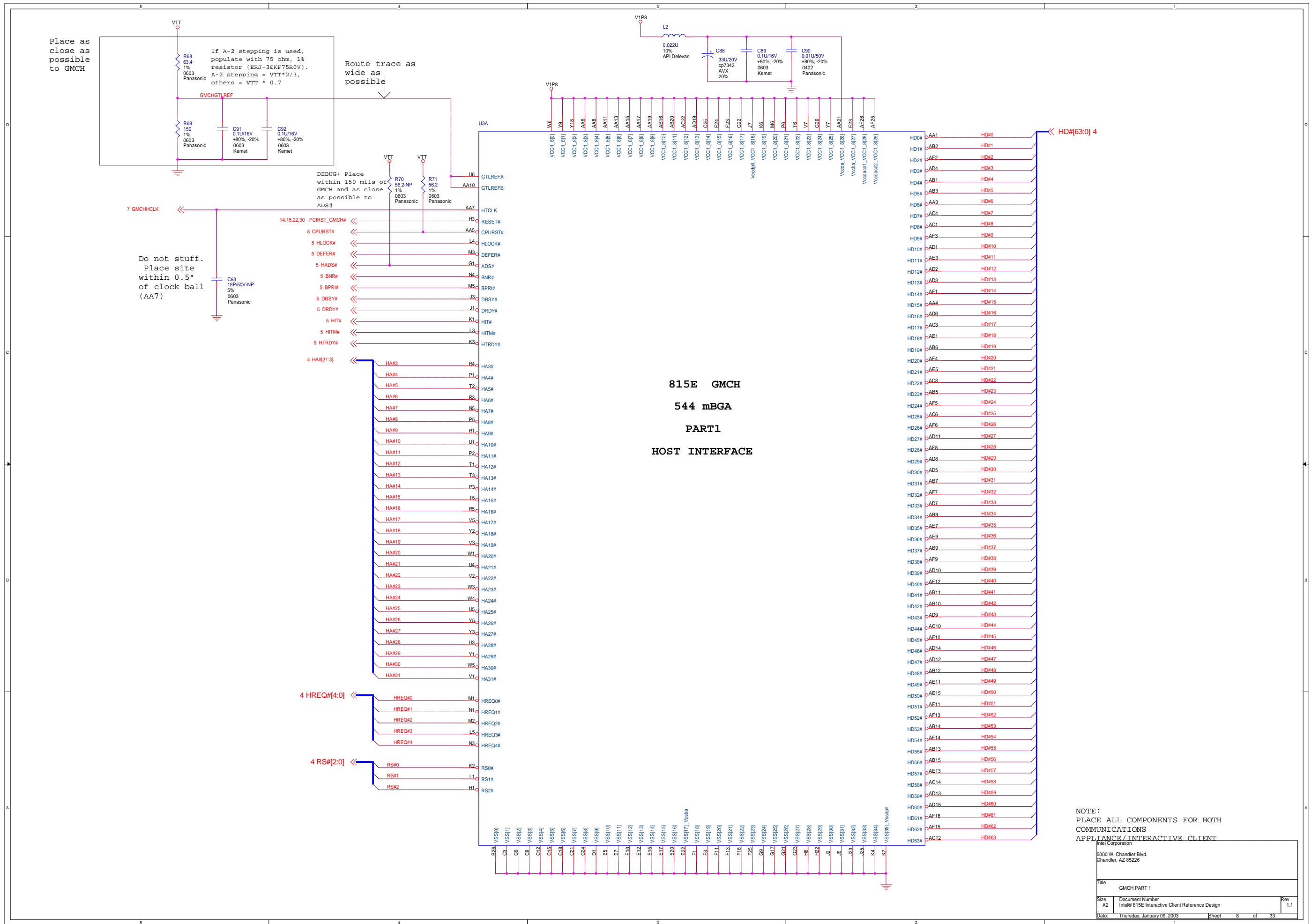


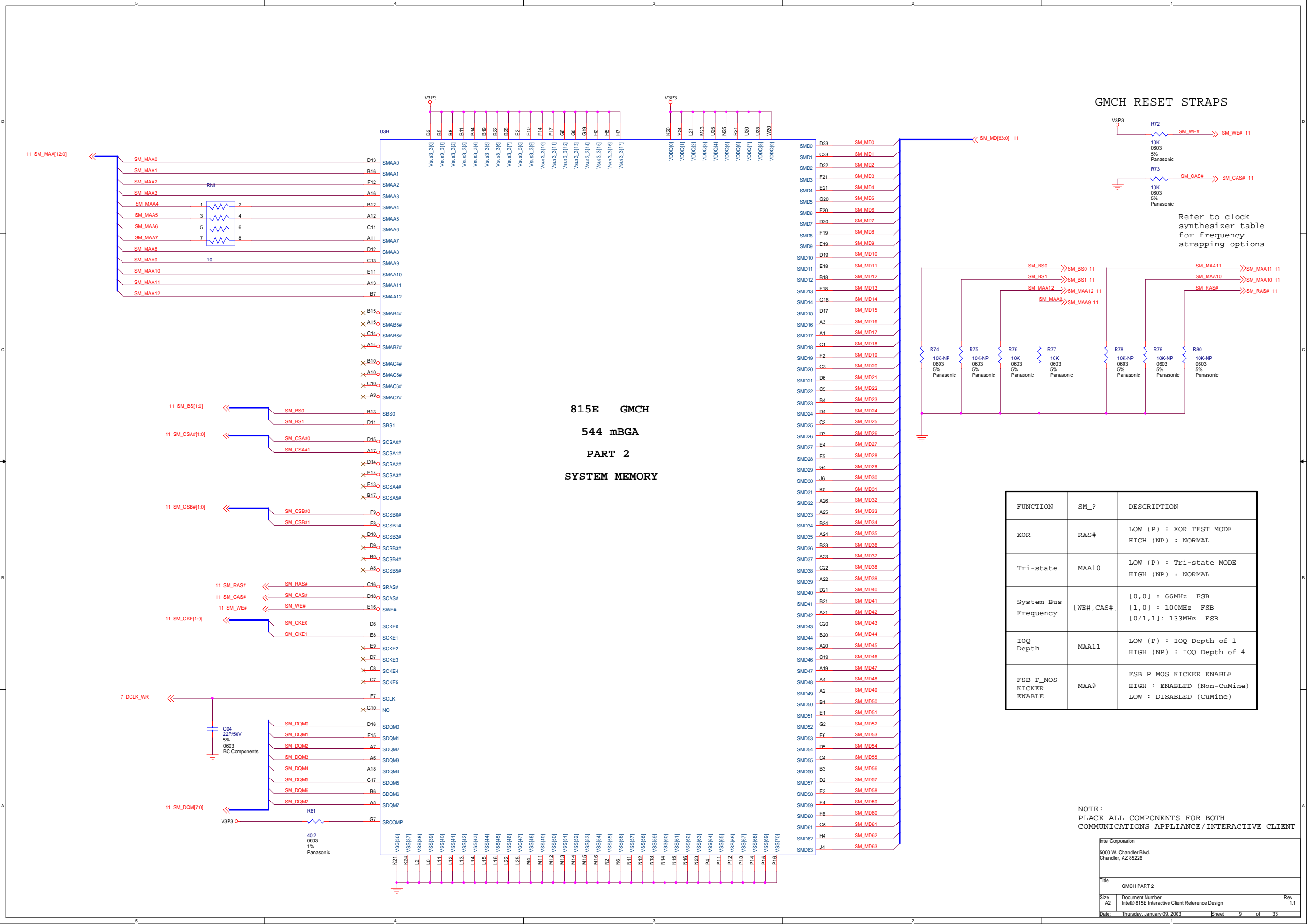
FS3	FS2	CPU MHz	SDRAM MHz
0	0	66	100
0	1	100	100
1	0	133	133
1	1	133	100

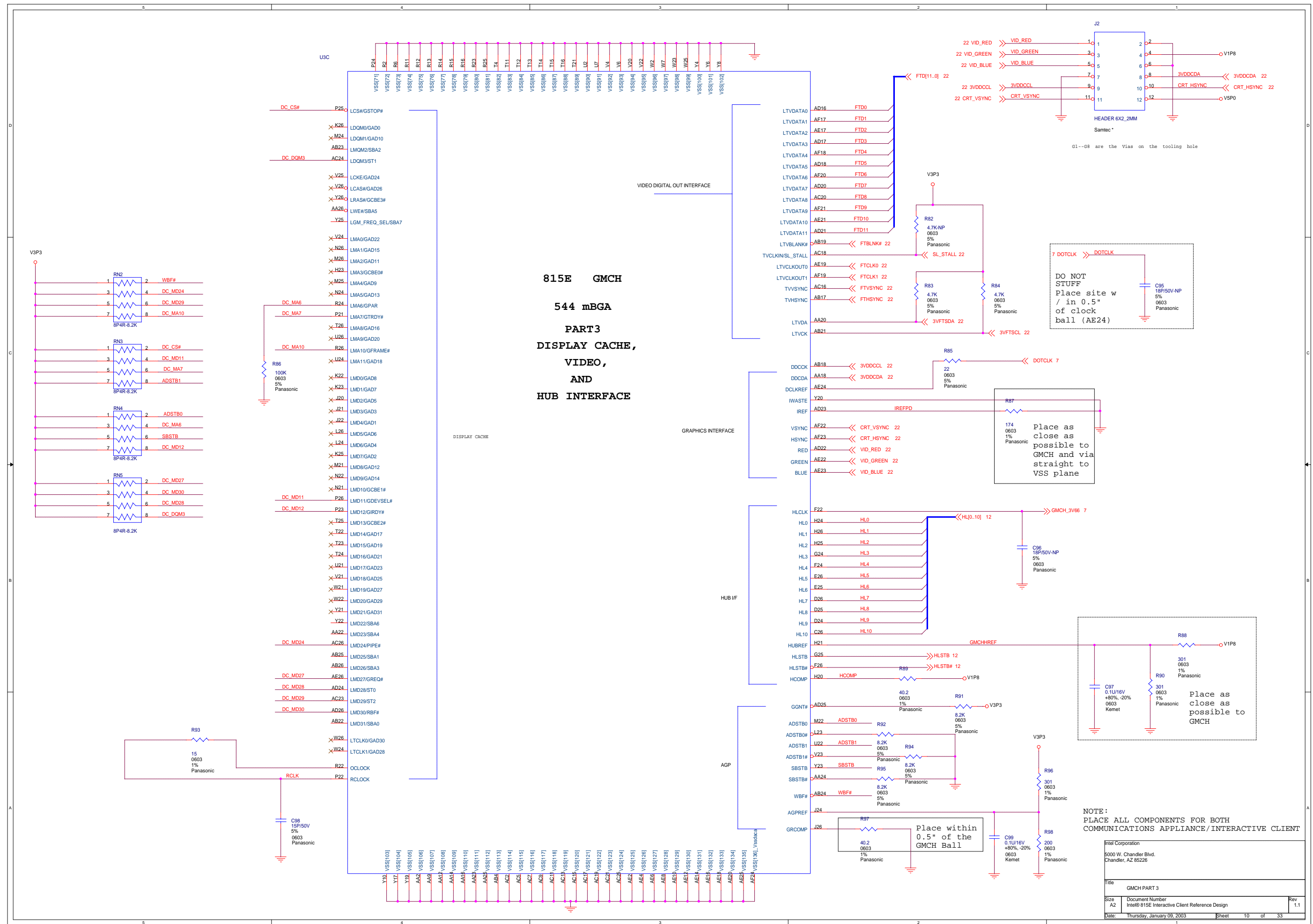
Note : 1 --> High ; 0 --> Low
BIOS will assign SDRAM memory clock when FSB is 133MHz

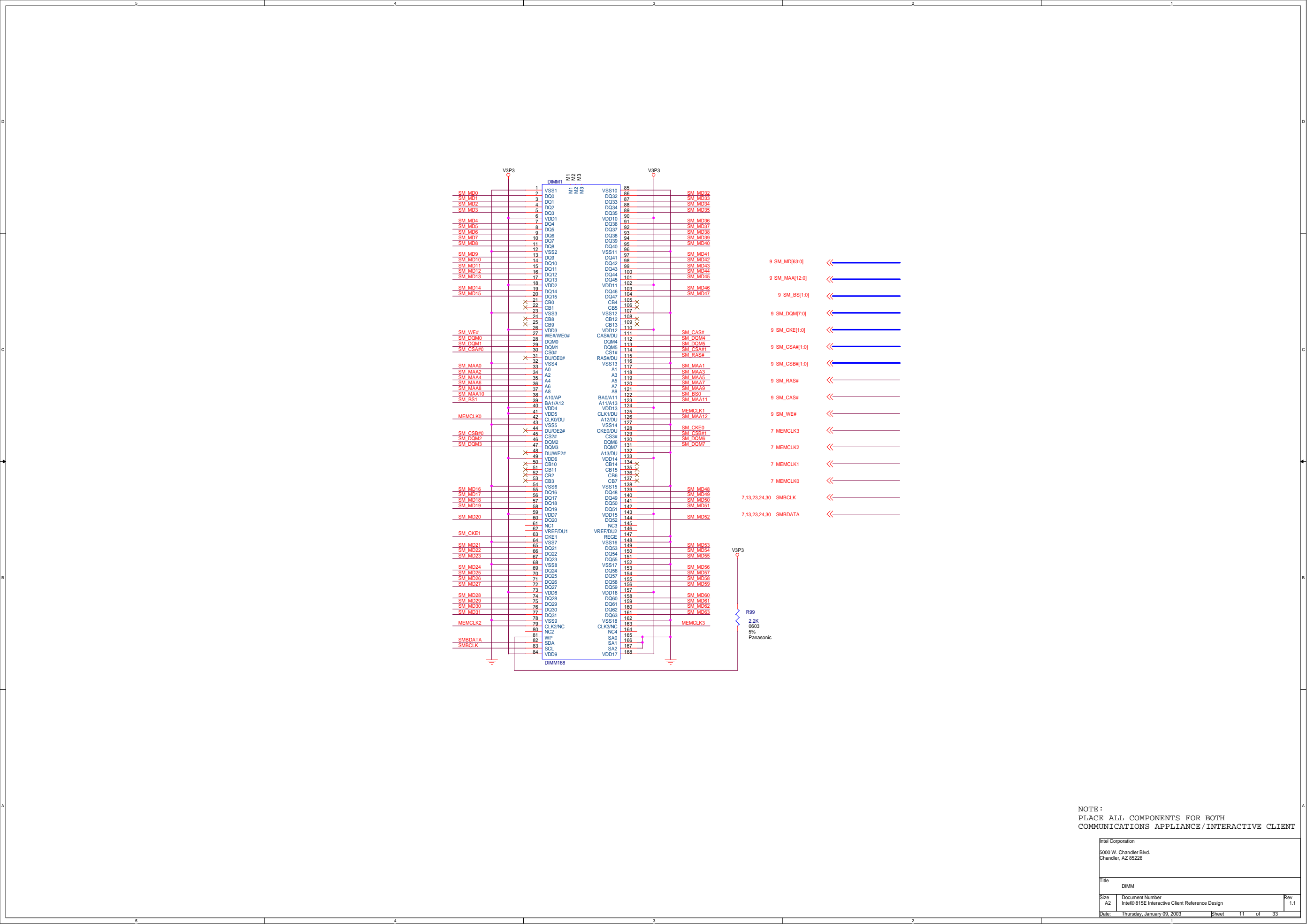
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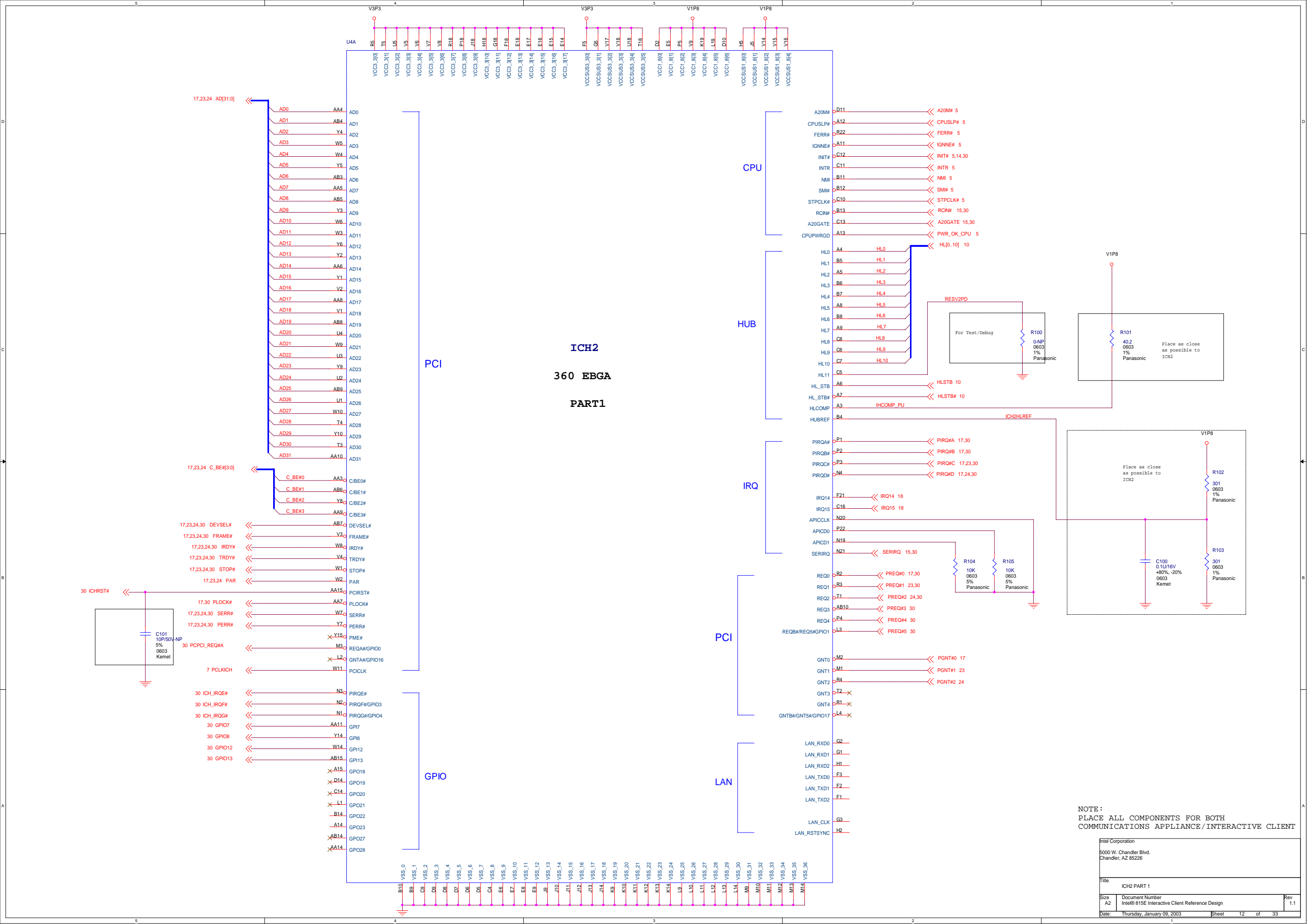


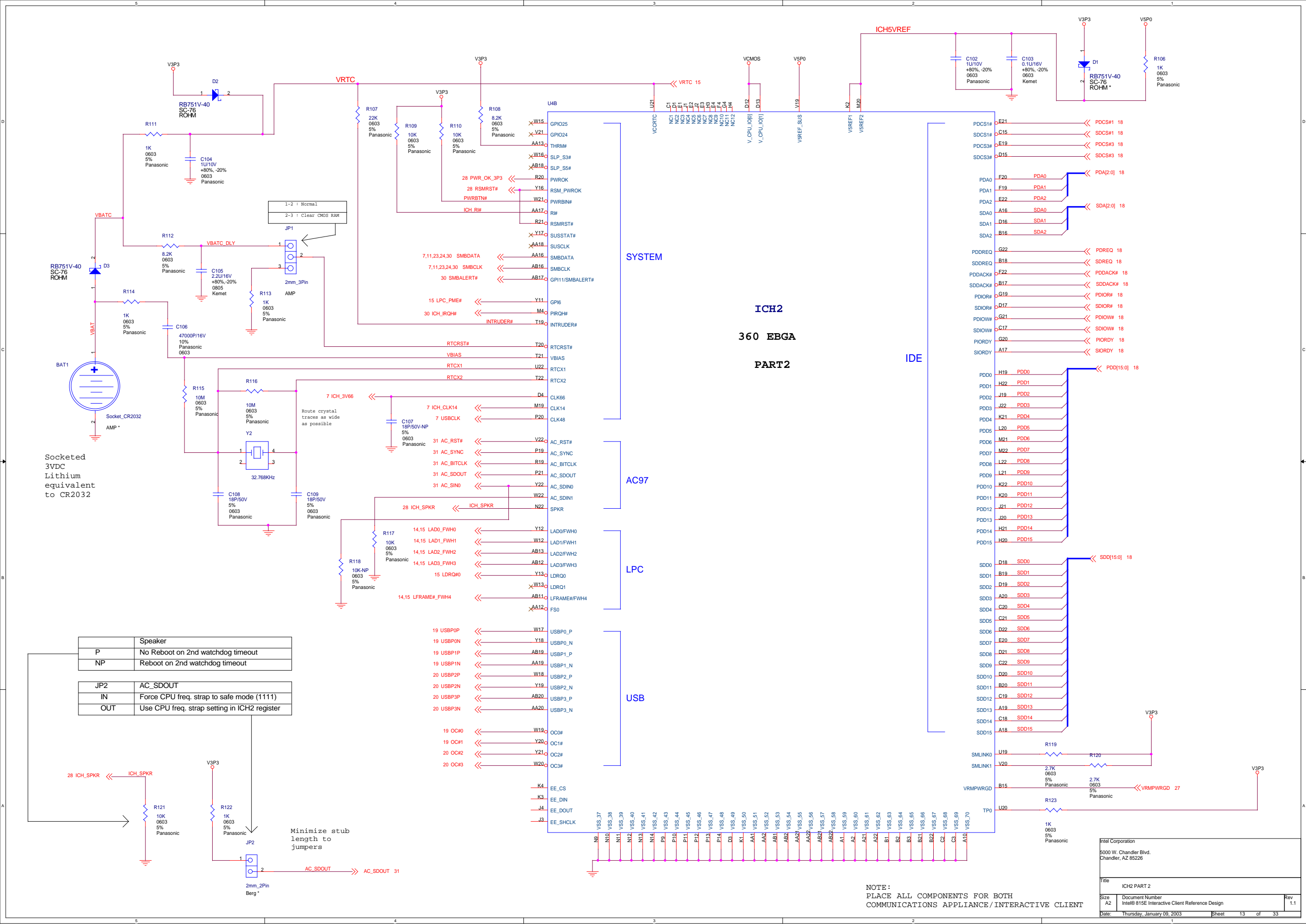




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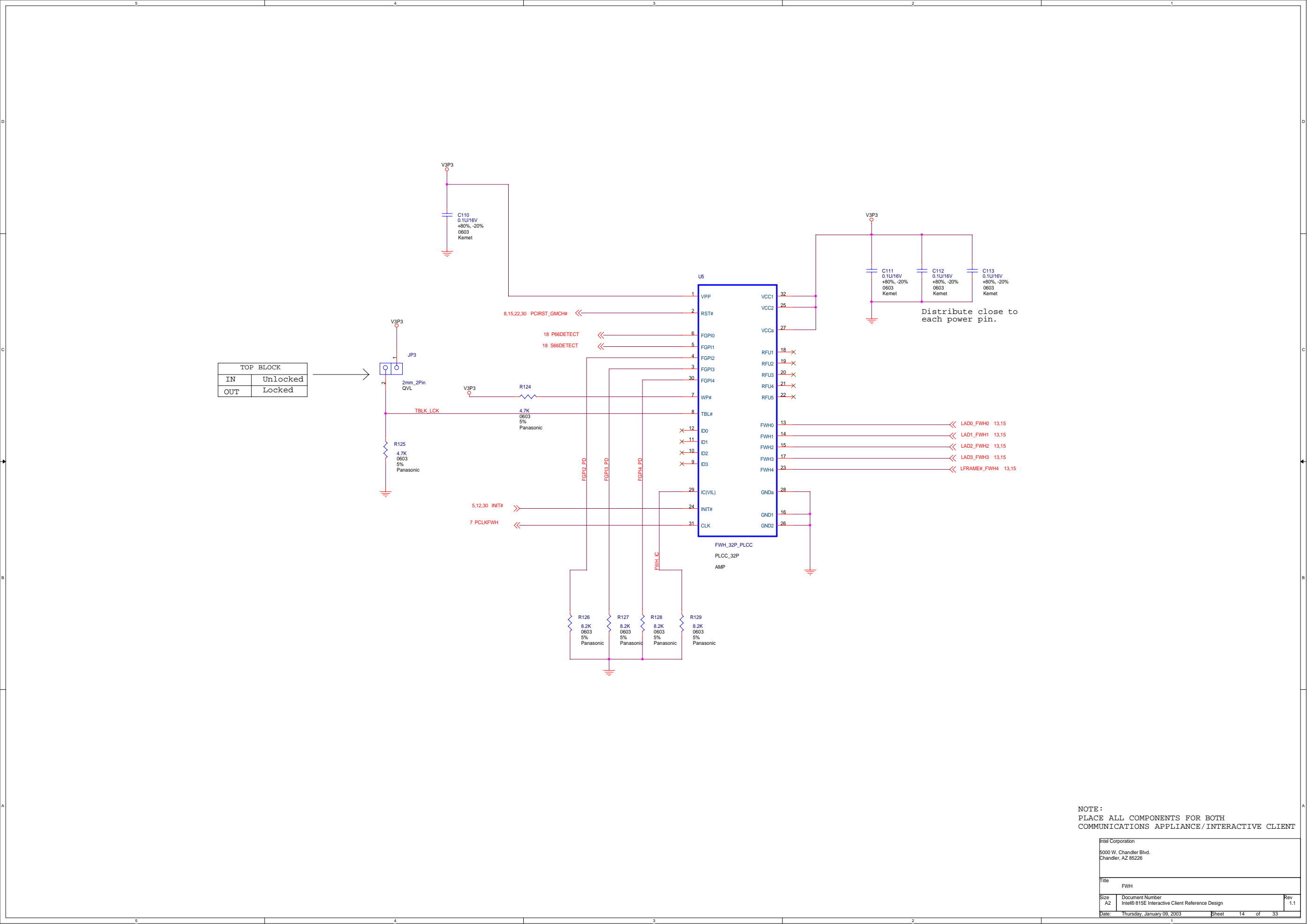
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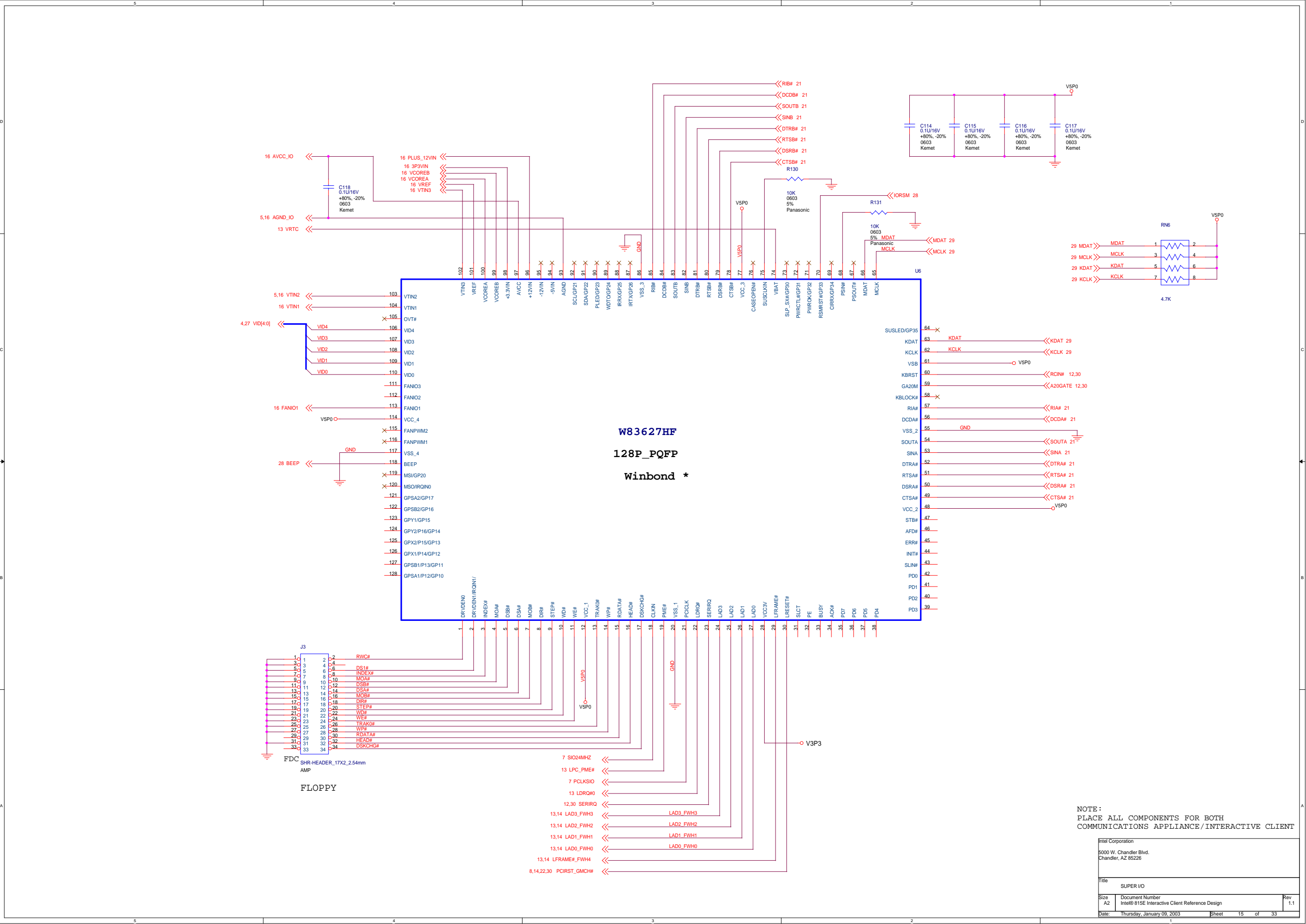
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15 VREF

15 VTIN

15 VTIN1

R139
30K
1210
1%
Panasonic

R134
10K
1210
1%
Panasonic

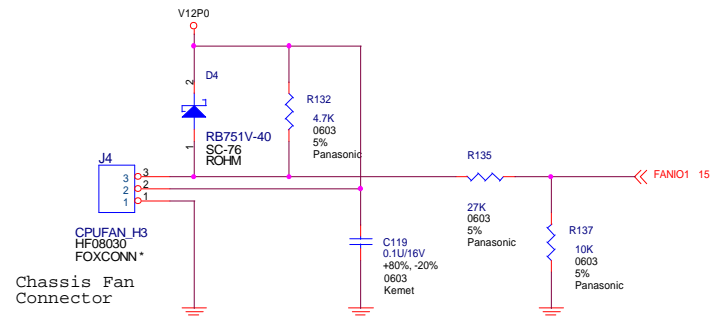
RT1
10K
Semitec *
1%
thm_150x95_100

R140
10K
0603
5%
Panasonic

R141
10K
0603
5%
Panasonic

C120
3300PF/50V
10%
0805
Panasonic

RT1: Sense
System
Temperature



VCORE

R133

10K
0603
5%
Panasonic

VCOREA 1.5

V1P8

R136

10K
0603
5%
Panasonic

V1P8B 1.8

V3P3

R138

10K
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5%
Panasonic

3P3VIN 1.5

V12P0

R142

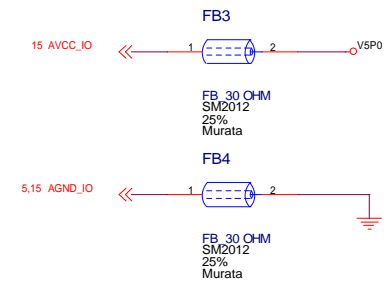
28K
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Panasonic

R143

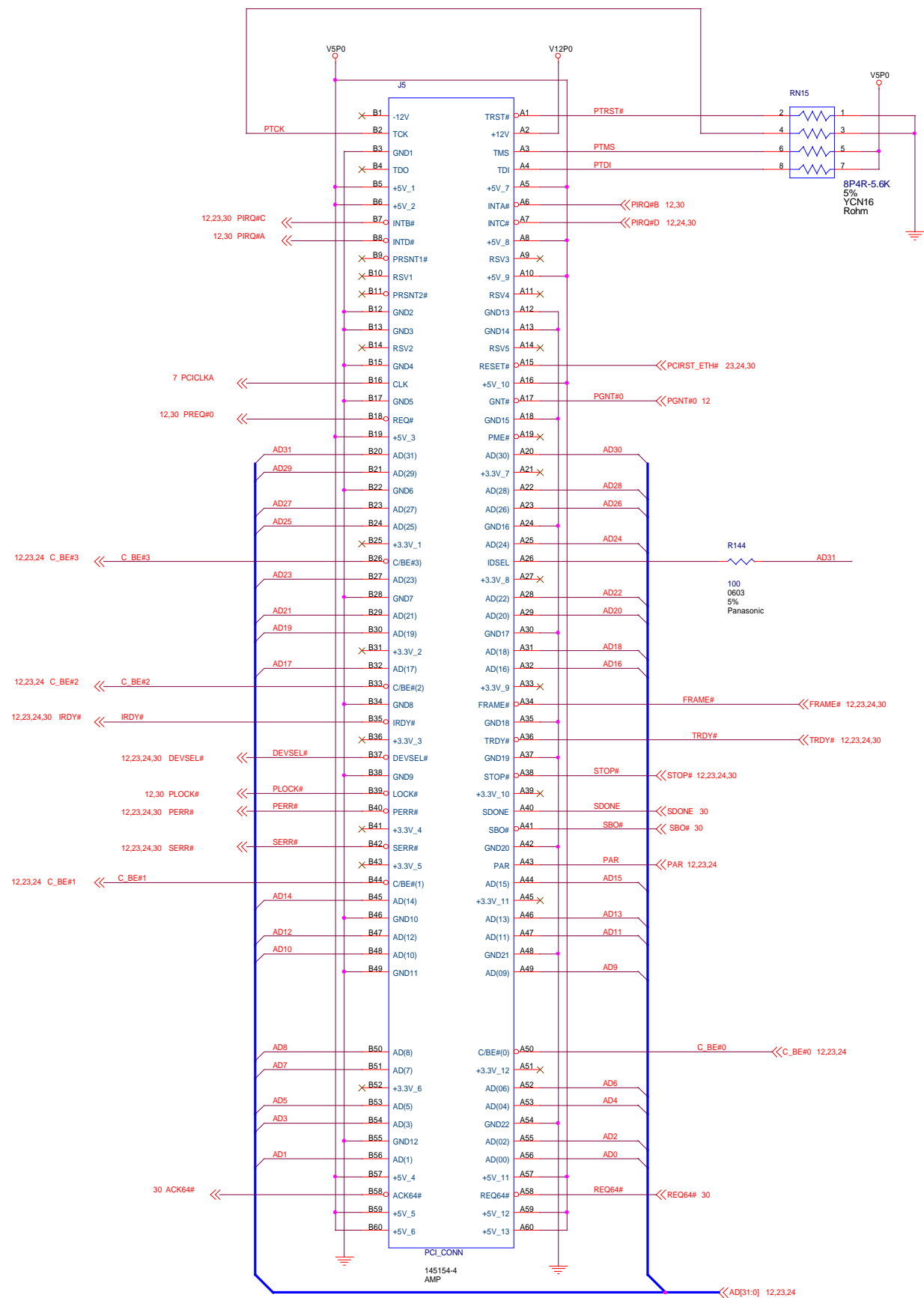
10K
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Panasonic

PLUS_12VIN 15

AGND_IO 5.15



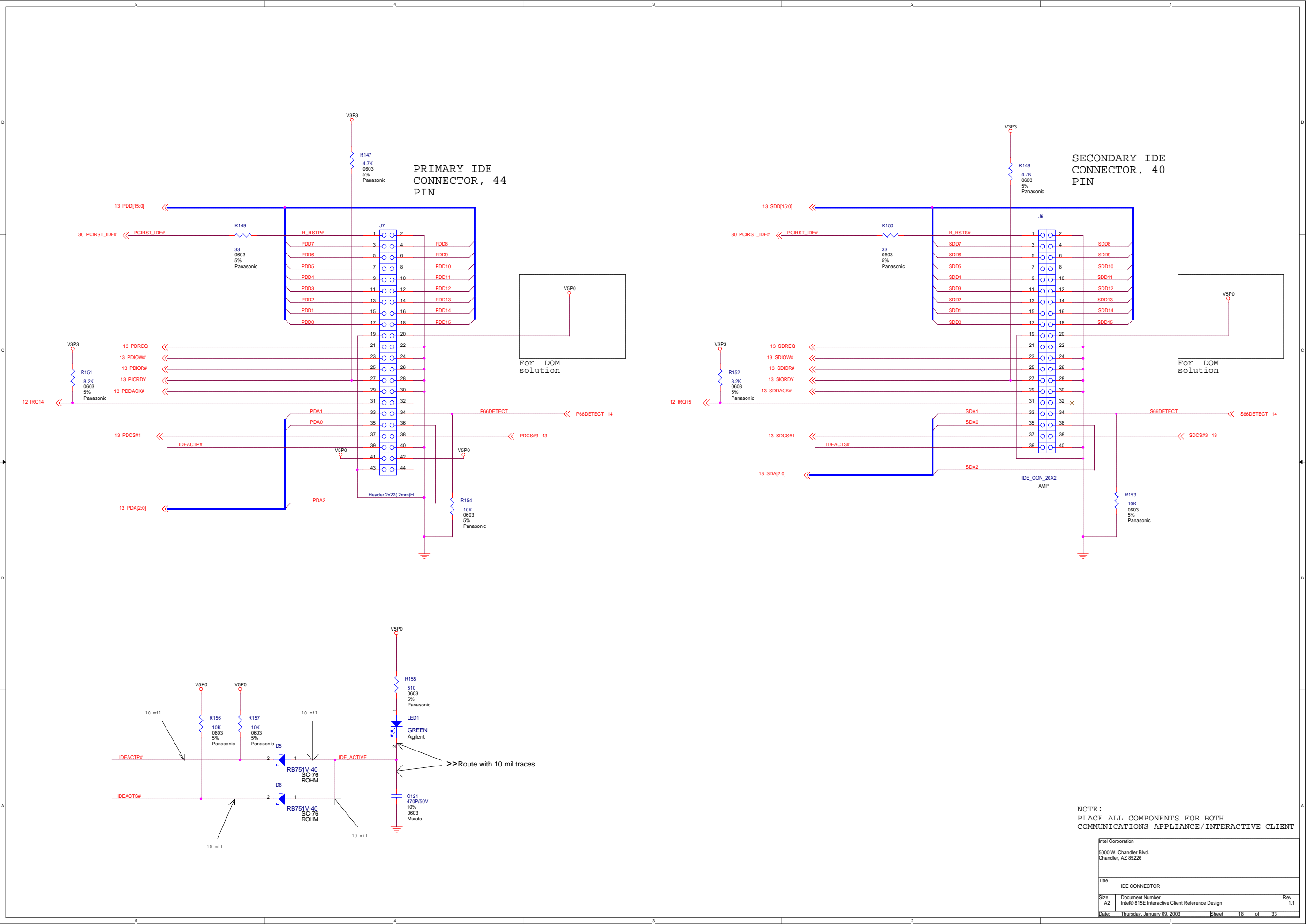
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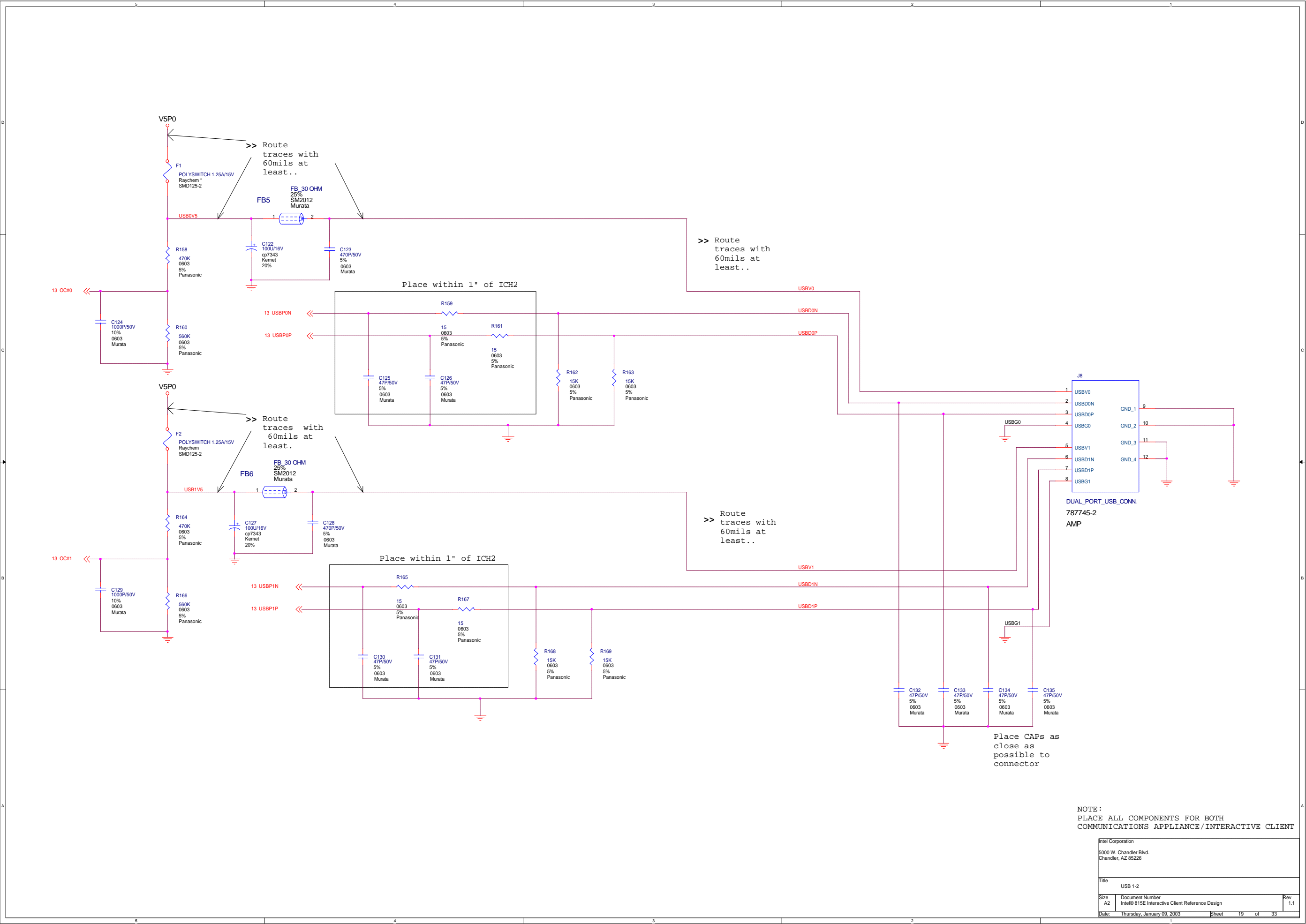


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5V PCI CONN., NO 3.3V AND -12V SUPPORT
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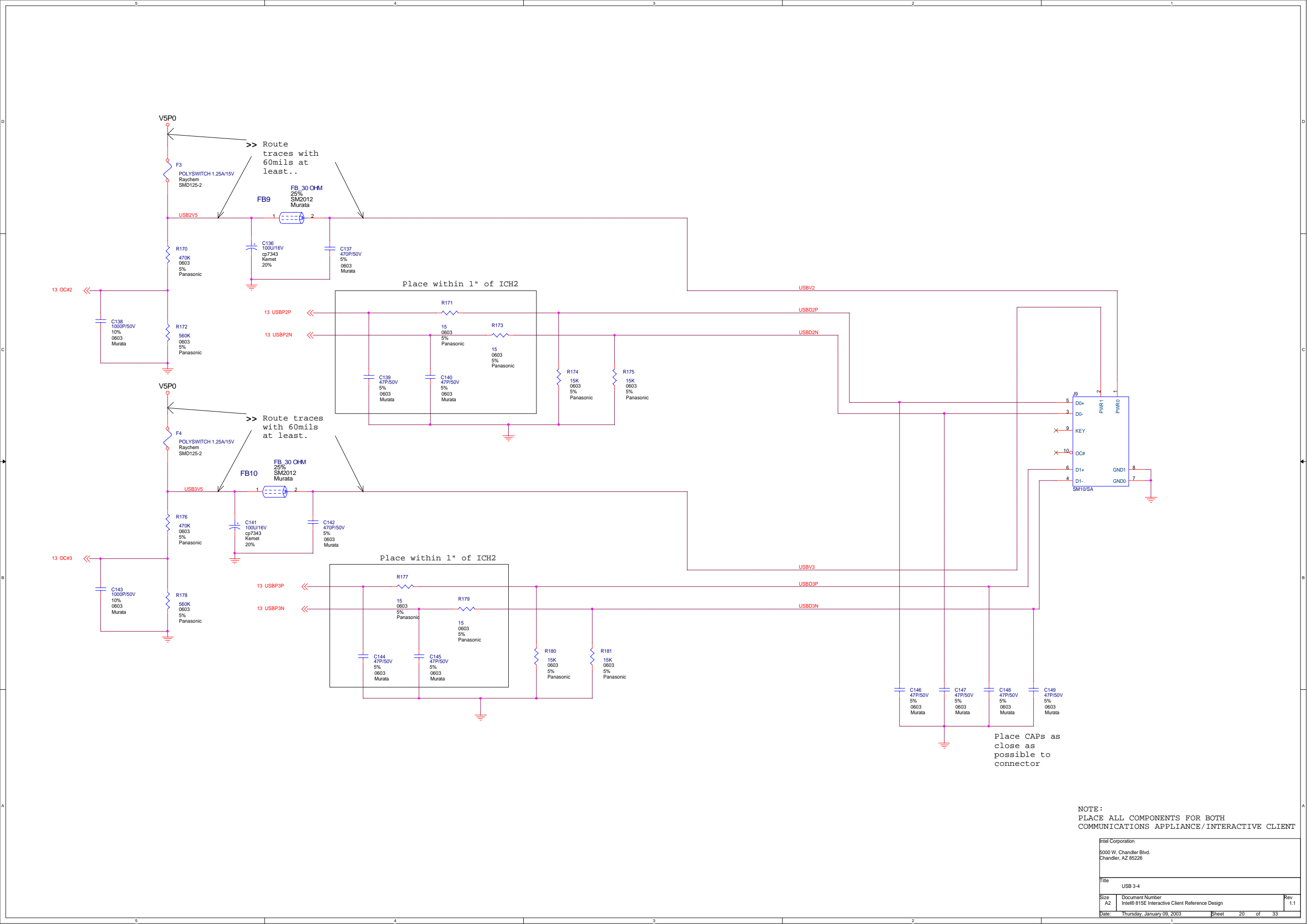
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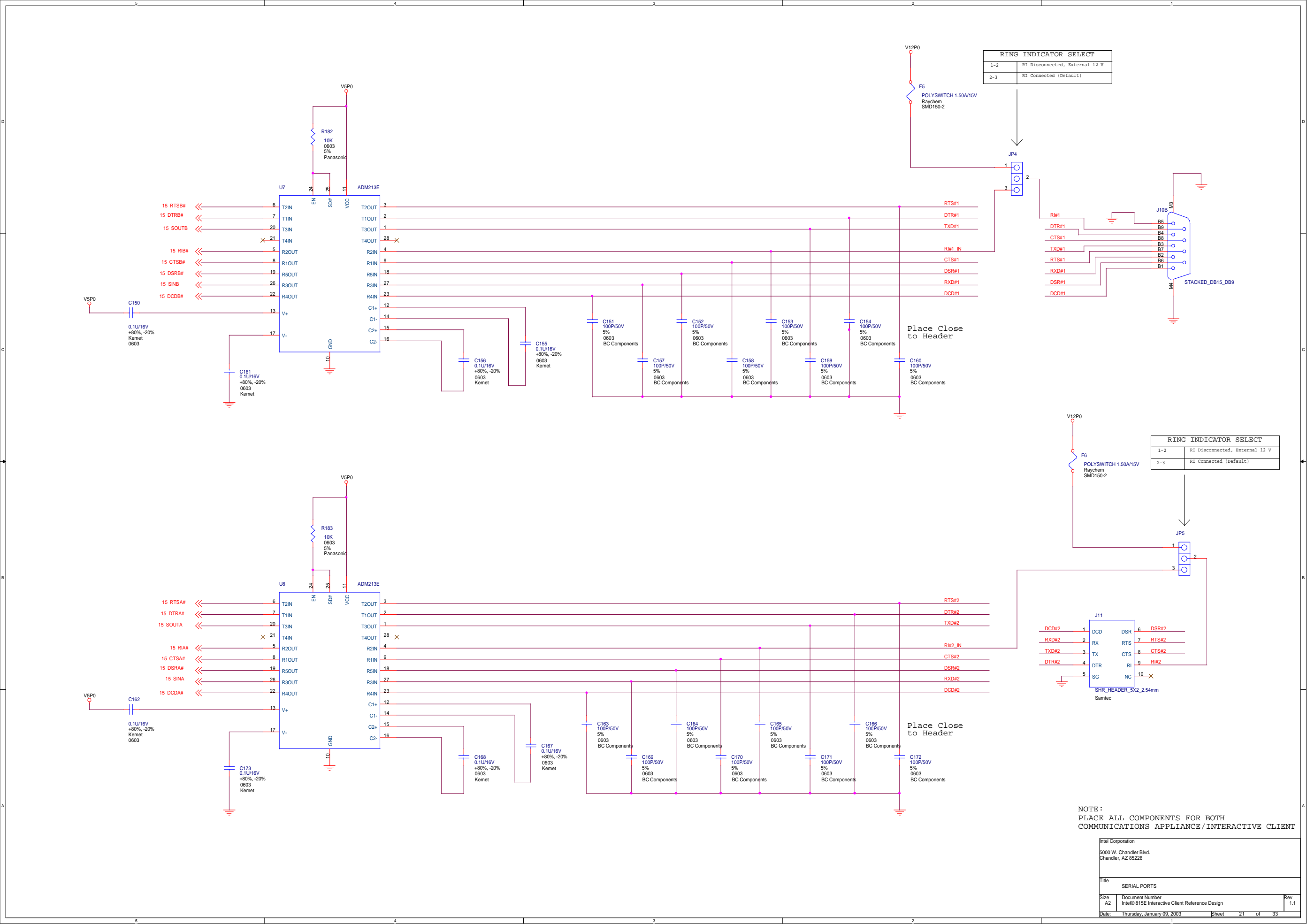
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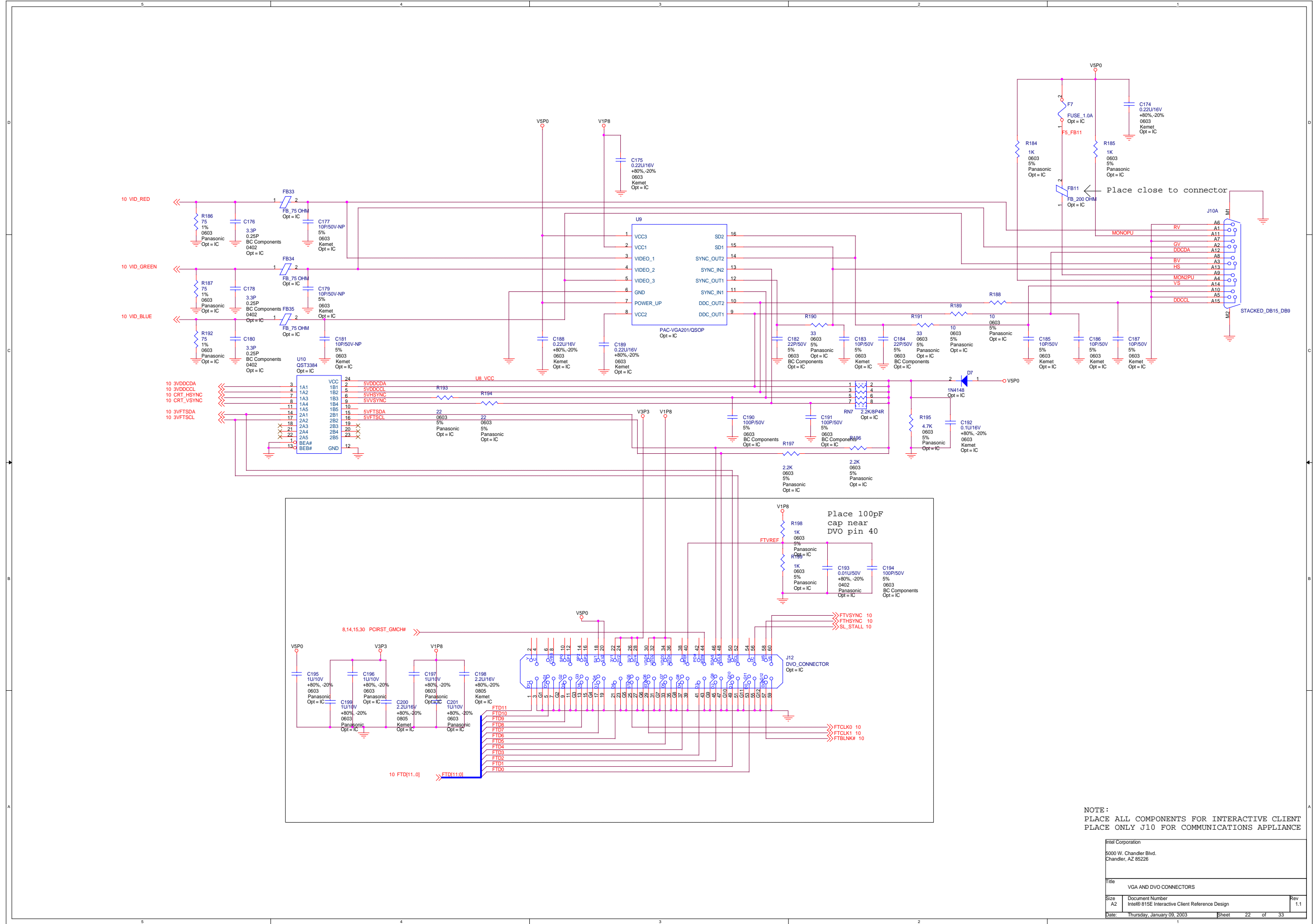
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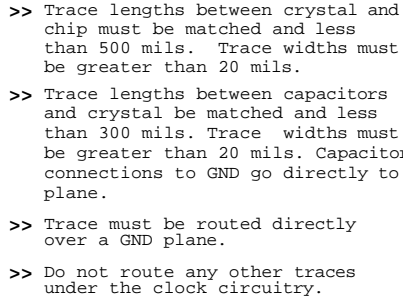
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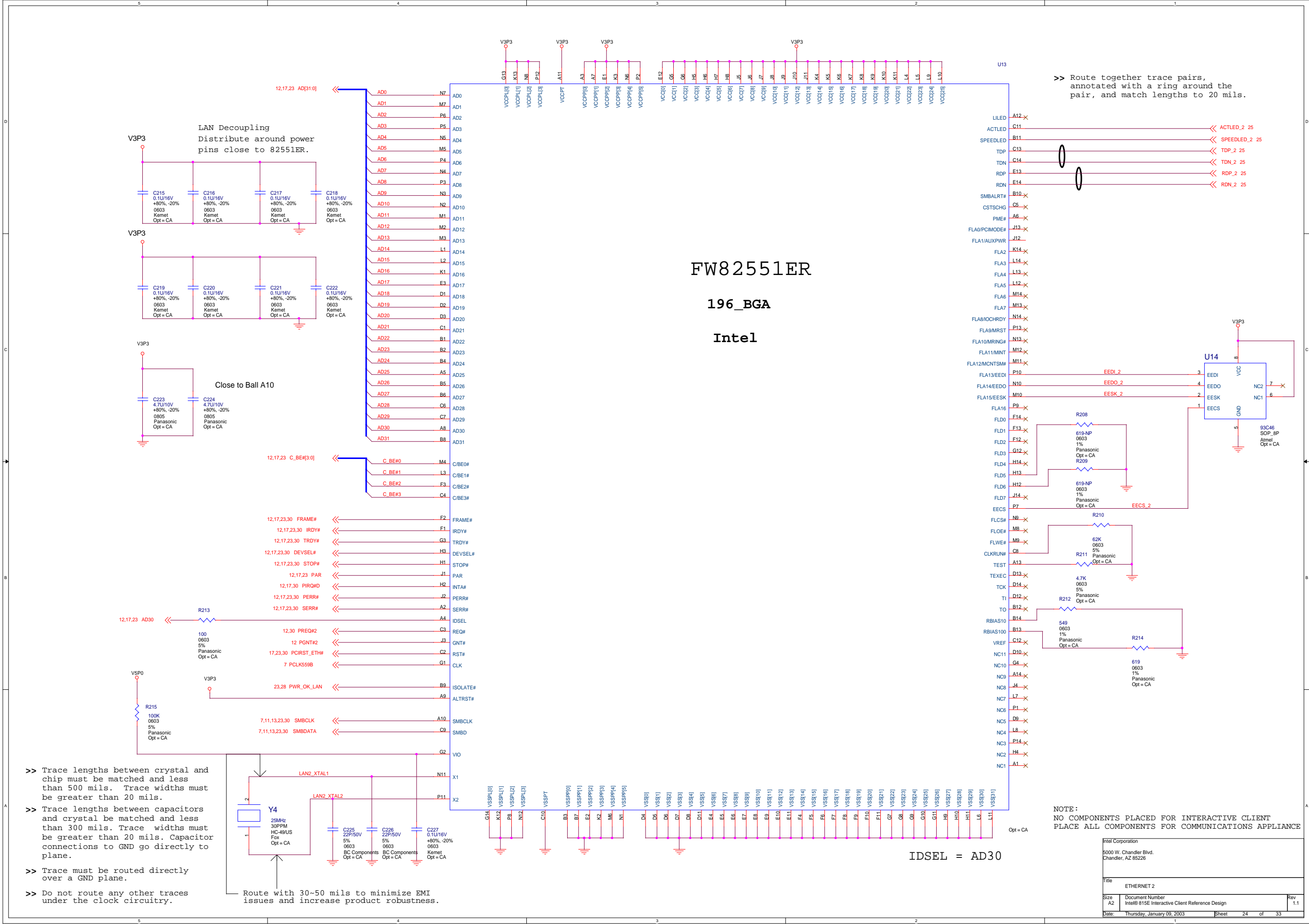
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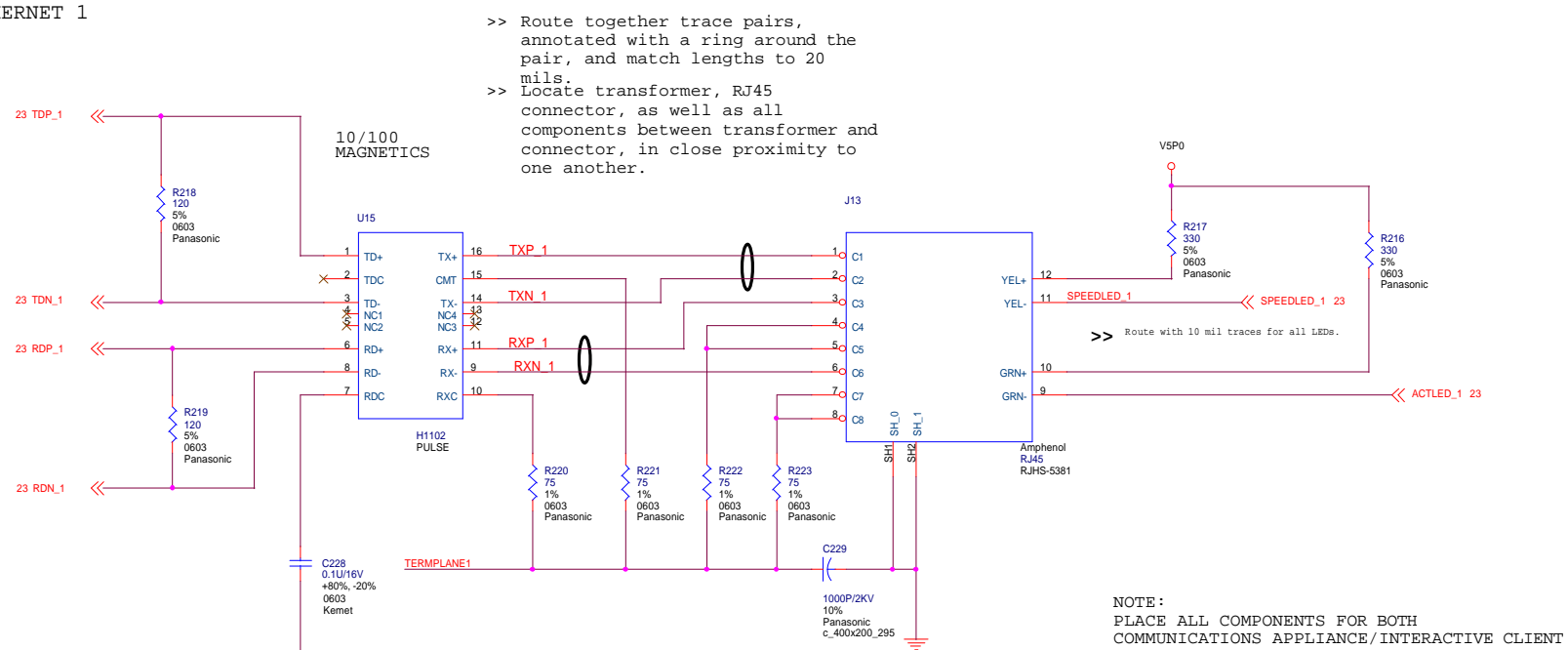


Route with 30~50 mils to minimize EMI issues and increase product robustness.

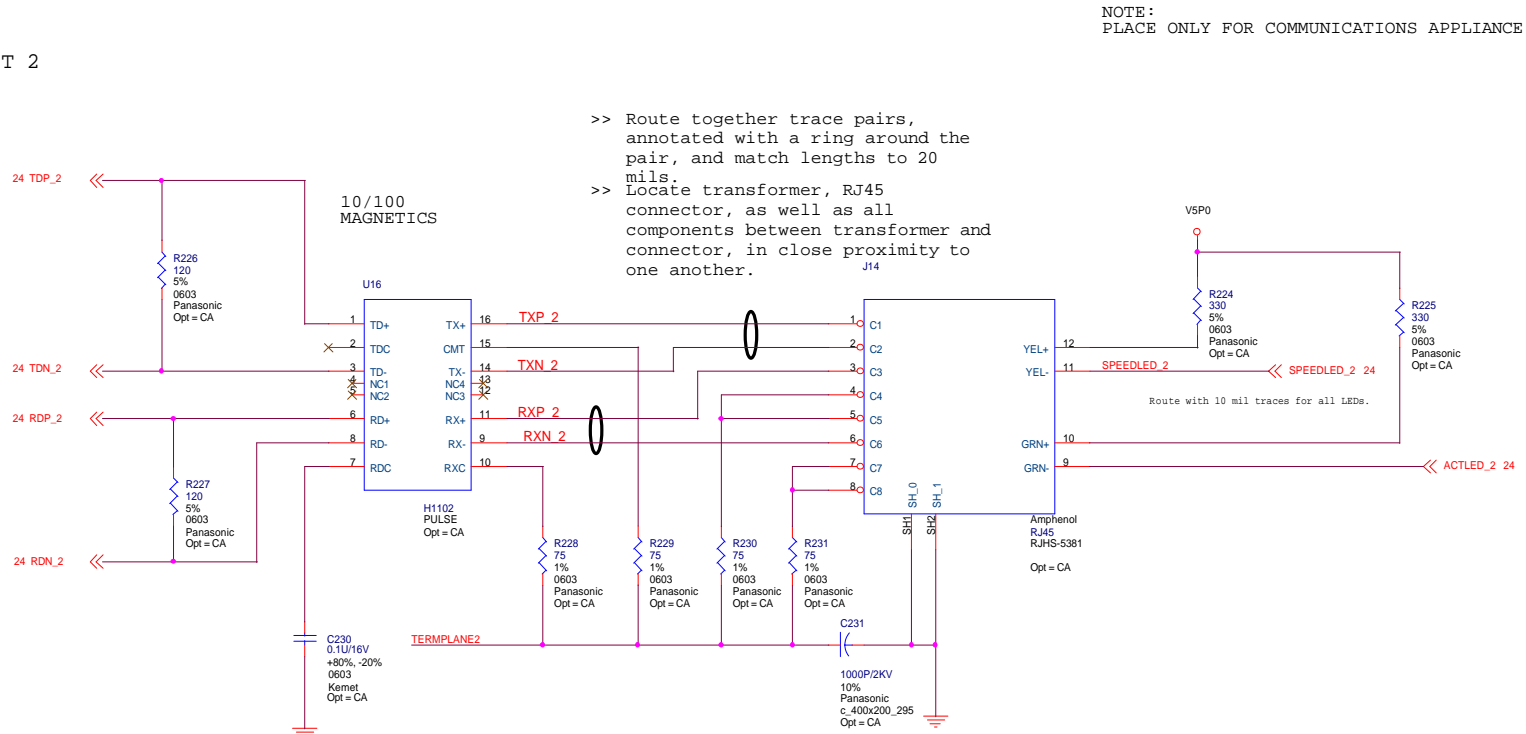
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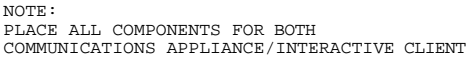


ETHERNET 1

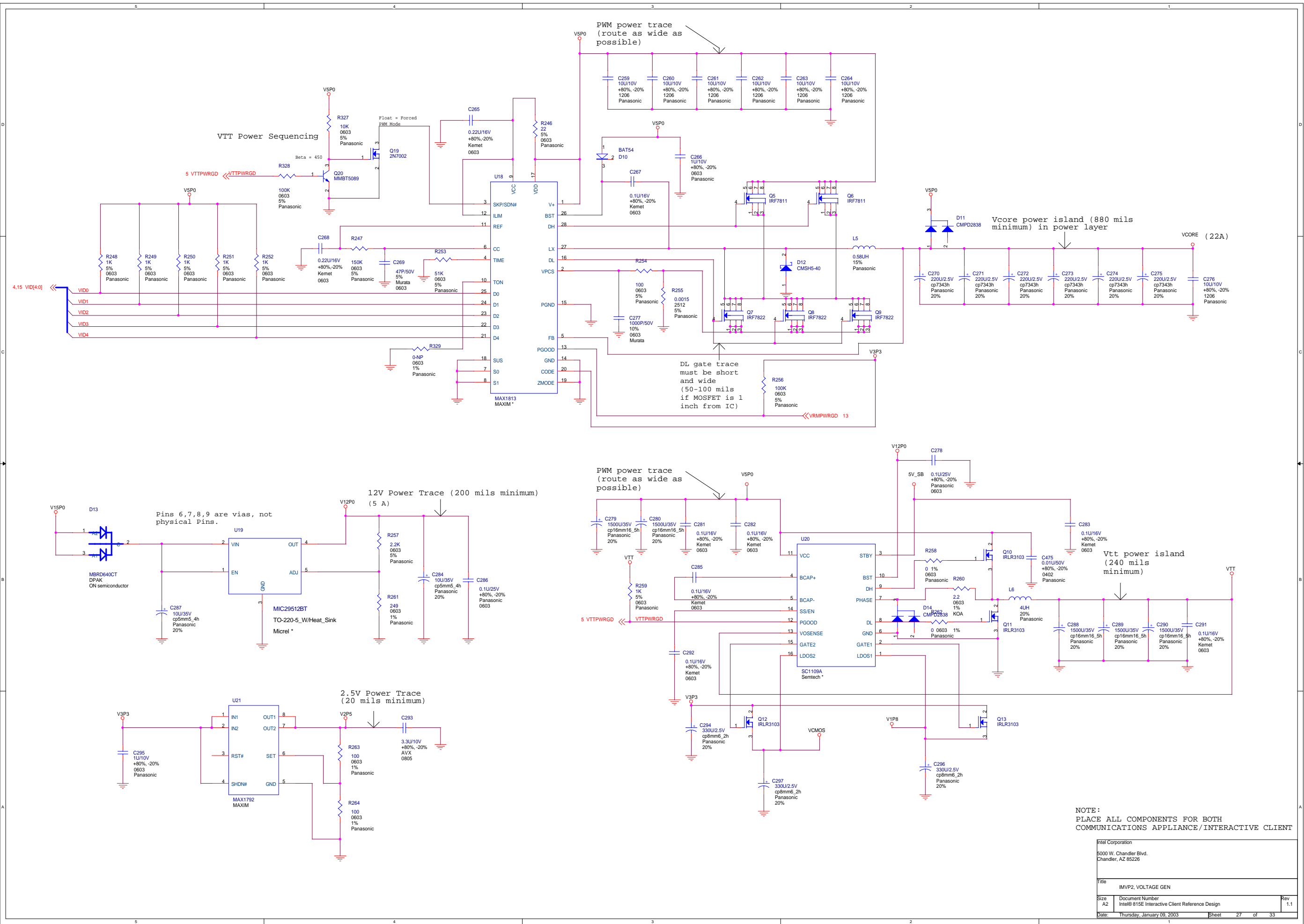


ETHERNET 2

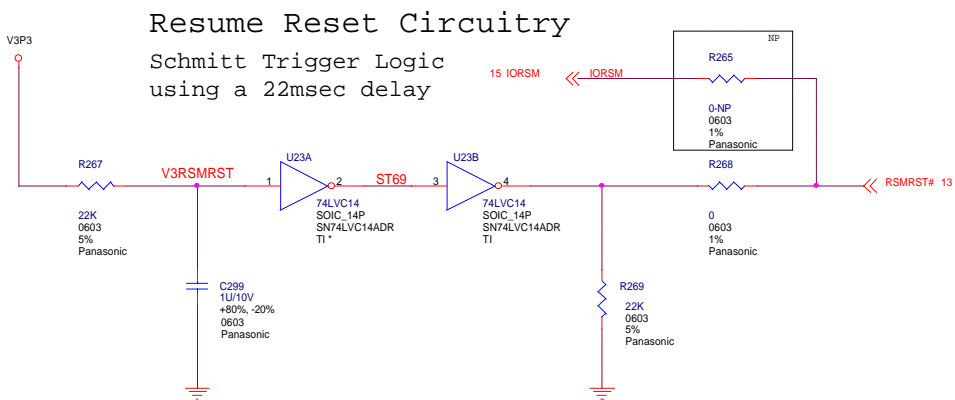




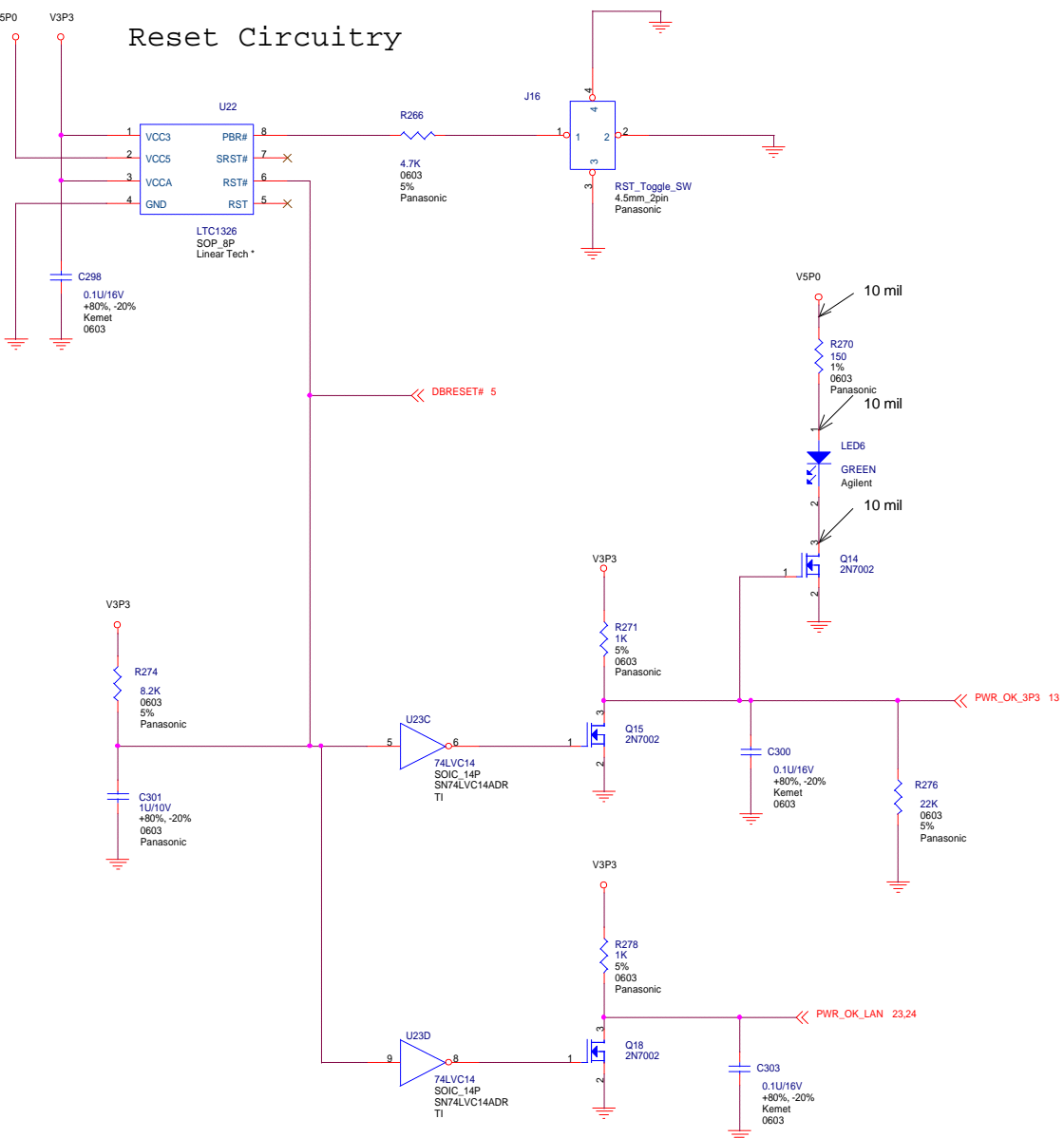
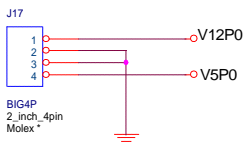
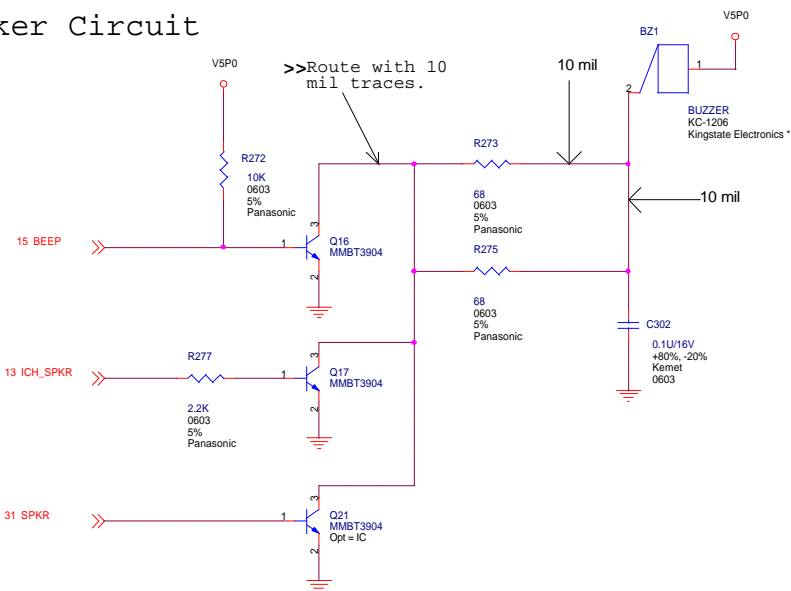
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Power Connector and Reset Control

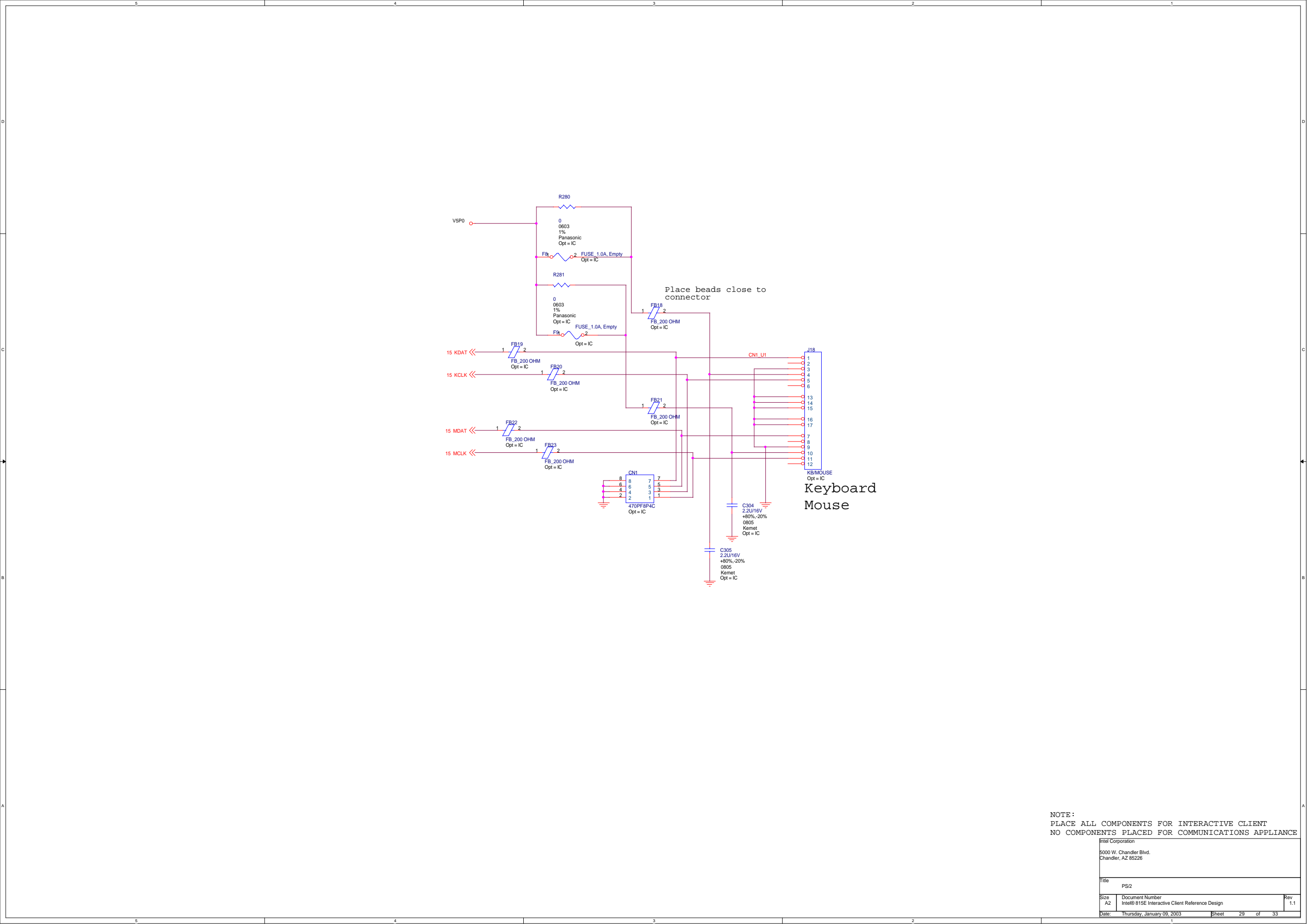


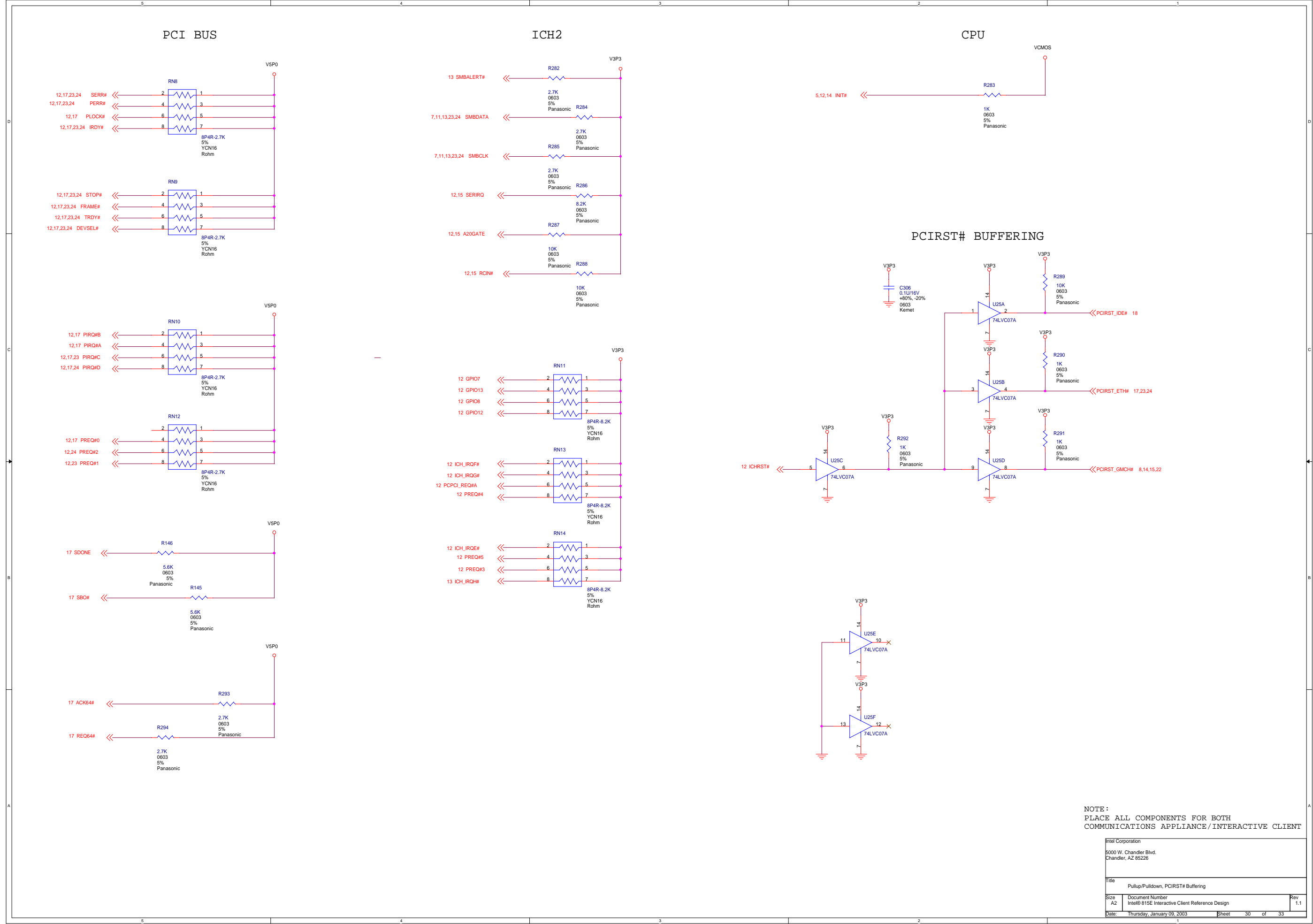
Speaker Circuit

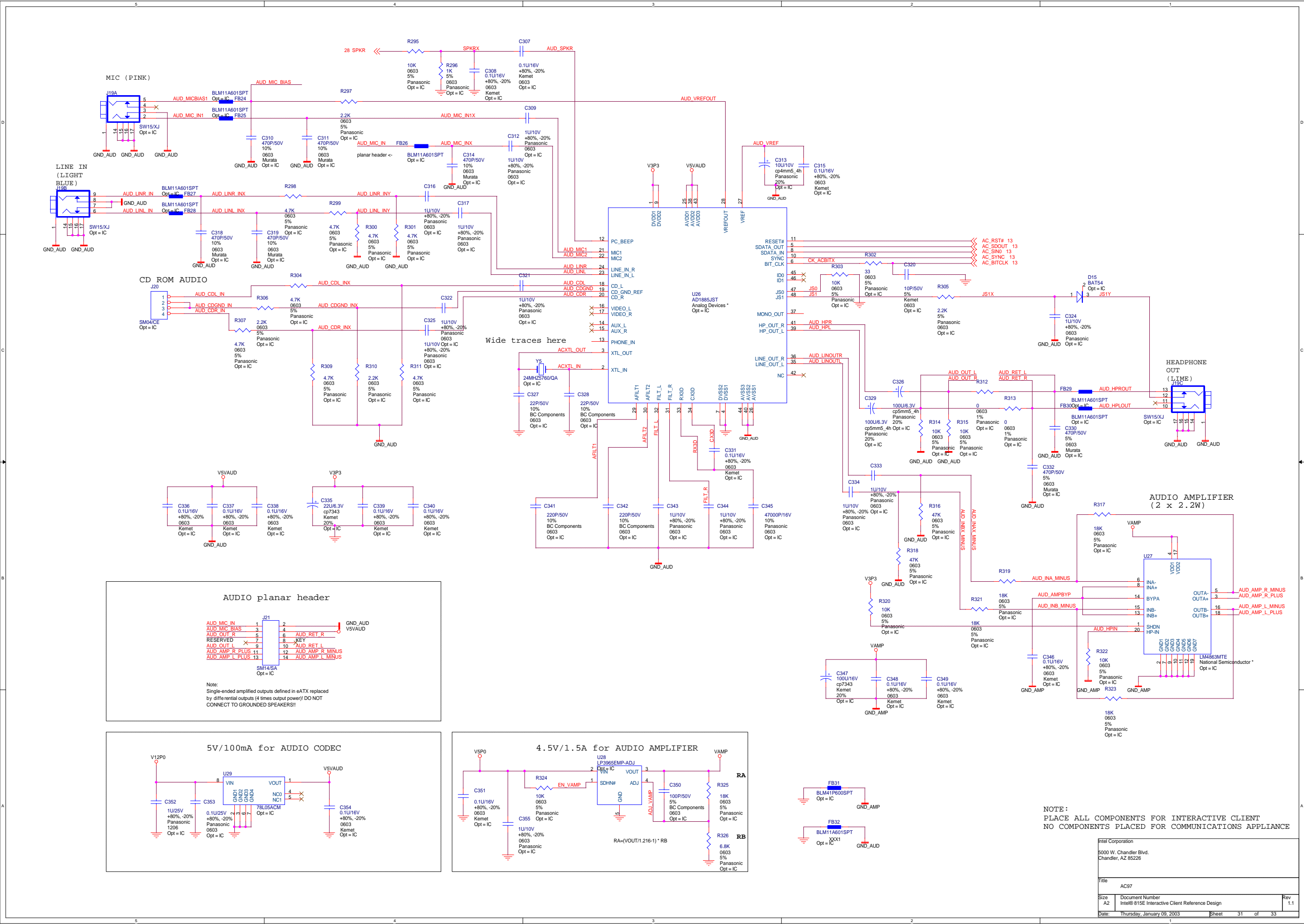


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PLACE ALL COMPONENTS FOR INTERACTIVE CLIENT
PLACE ALL BUT Q21 FOR COMMUNICATIONS APPLIANCE

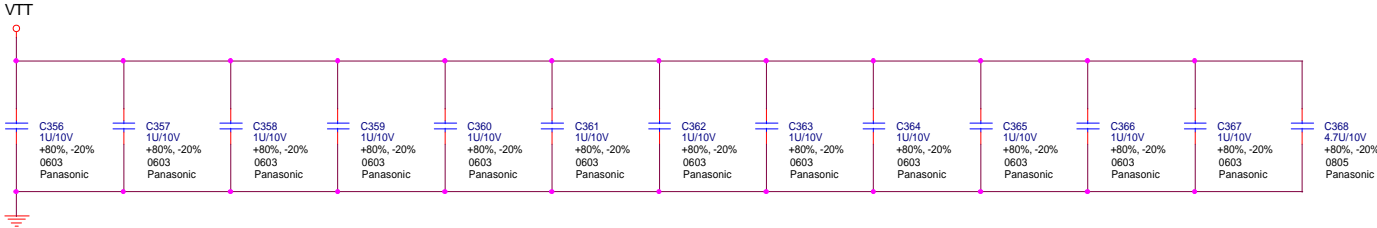
Intel Corporation 5000 W. Chandler Blvd. Chandler, AZ 85226		
Title POWER CONNECTOR		
Size A2	Document Number Intel® 815E Interactive Client Reference Design	Rev 1.1
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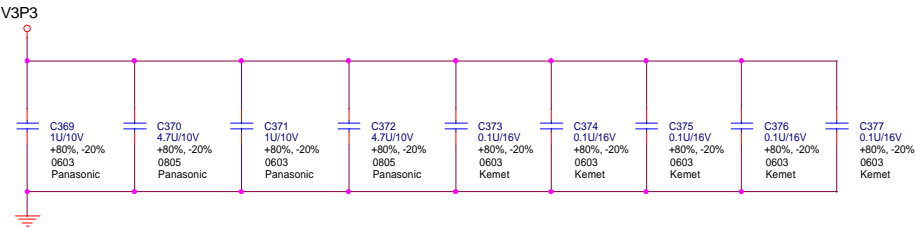




VTT Power Decoupling

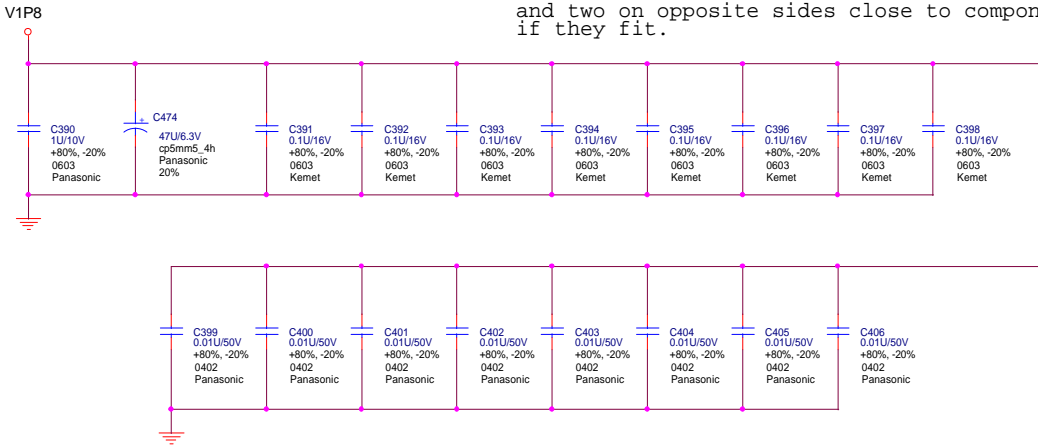


Misc. Power Decoupling



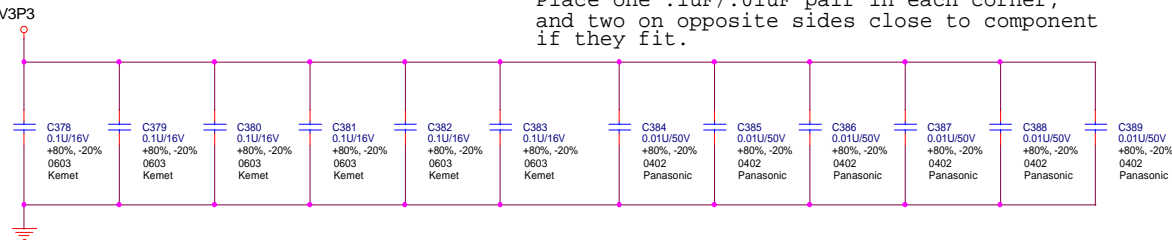
GMCH Decoupling

GMCH Core Plane Decoupling:
Place one .1uF/.01uF pair in each corner,
and two on opposite sides close to component
if they fit.

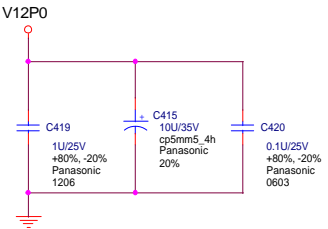
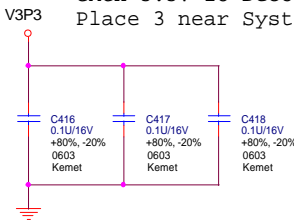


ICH2 Decoupling

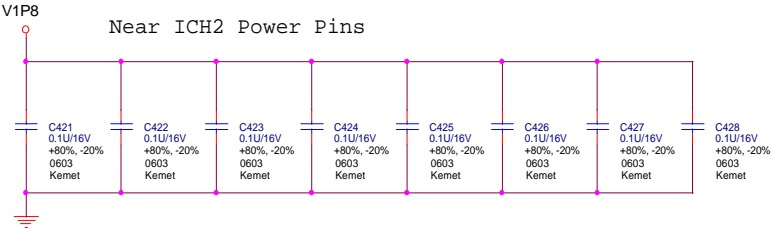
ICH2 3.3V Plane Decoupling:
Place one .1uF/.01uF pair in each corner,
and two on opposite sides close to component
if they fit.



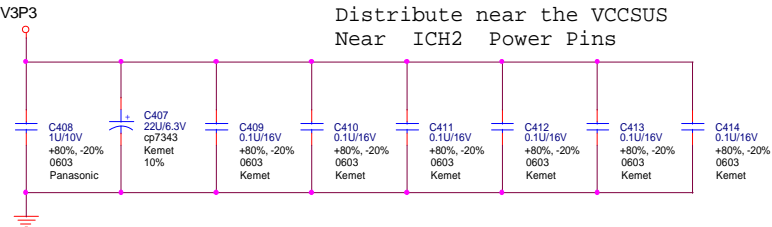
GMCH 3.3V IO Decoupling:
Place 3 near System Memory Quadrant



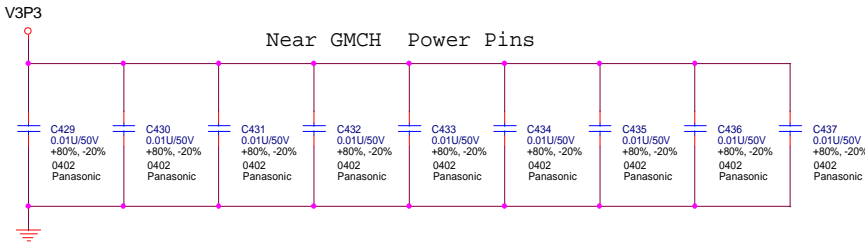
Near ICH2 Power Pins



Distribute near the VCCSUS
Near ICH2 Power Pins

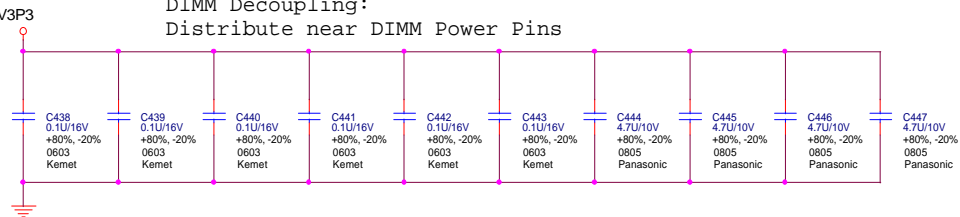


Near GMCH Power Pins

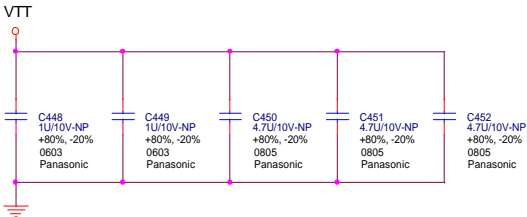


System Memory Decoupling

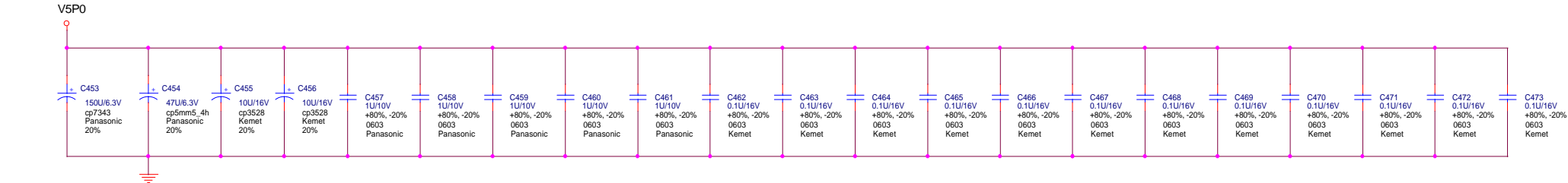
DIMM Decoupling:
Distribute near DIMM Power Pins



VTT Power Decoupling



V5P0 Decoupling



NOTE:
PLACE ALL COMPONENTS FOR BOTH
COMMUNICATIONS APPLIANCE/INTERACTIVE CLIENT

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J1: ITP (15x2) Connector

P.N.	Description	P.N.	Description
1	Ground	2	CPURST#
3	Ground	4	DBRESET#
5	Ground	6	TCK
7	TDI	8	TMS
9	TDO	10	VTT
11	TRST#	12	VTT
13	N/C	14	Ground
15	PREQ#	16	Ground
17	PRDY#	18	Ground
19	N/C	20	Ground
21	N/C	22	Ground
23	N/C	24	Ground
25	N/C	26	Ground
27	N/C	28	Ground
29	N/C	30	Ground

J2: VGA Board (6x2) Connector

P.N.	Description	P.N.	Description
1	VID_RED	2	Ground
3	VID_GREEN	4	V1P8
5	VID_BLUE	6	Ground
7	Ground	8	3VDDCDA
9	3VDDCCL	10	CRT_HSYNC
11	CRT_VSYNC	12	V5P0

J3: FDC(17x2) Connector

P.N.	Description	P.N.	Description
1	Ground	2	Density0#
3	Ground	4	N/C
5	Ground	6	Density1#
7	Ground	8	INDEX#
9	Ground	10	MOA#
11	Ground	12	DSB#
13	Ground	14	DSA#
15	Ground	16	MOB#
17	Ground	18	DIR#
19	Ground	20	STEP#
21	Ground	22	WD#
23	Ground	24	WE#
25	Ground	26	TRACK0#
27	Ground	28	WP#
29	N/C	30	RDATA#
31	Ground	32	HEAD#
33	N/C	34	DSKCHG#

J4: Tachometer FAN Connector

Pin Number	Signal Description
1	Ground
2	V12P0
3	Tachometer Signal

J5: PCI BUS CONNECTOR

P.N.	Description	P.N.	Description
B1	N/C	A1	PTRST#
B2	PTCK	A2	V12P0
B3	Ground	A3	PTMS
B4	N/C	A4	PTDI
B5	V5P0	A5	V5P0
B6	V5P0	A6	PIRQ#B
B7	PIRQ#C	A7	PIRQ#D
B8	PIRQ#A	A8	V5P0
B9	N/C	A9	N/C
B10	N/C	A10	V5P0
B11	N/C	A11	N/C
B12	Ground	A12	Ground
B13	Ground	A13	Ground
B14	N/C	A14	N/C
B15	Ground	A15	PCIRST#
B16	PCICLK	A16	V5P0
B17	Ground	A17	PGNT#0
B18	PREQ#0	A18	Ground
B19	V5P0	A19	N/C
B20	AD31	A20	AD30
B21	AD29	A21	N/C
B22	Ground	A22	AD28
B23	AD27	A23	AD26
B24	AD25	A24	Ground
B25	N/C	A25	AD24
B26	C_BE#3	A26	IDSEL
B27	AD23	A27	N/C
B28	Ground	A28	AD22
B29	AD21	A29	AD20
B30	AD19	A30	Ground
B31	N/C	A31	AD18
B32	AD17	A32	AD16
B33	C_BE#2	A33	N/C
B34	Ground	A34	FRAME#
B35	IRDY#	A35	Ground
B36	N/C	A36	TRDY#
B37	DEVSEL#	A37	Ground
B38	Ground	A38	STOP#
B39	PLOCK#	A39	N/C
B40	PERR#	A40	SDONE
B41	N/C	A41	SBO#
B42	SERR#	A42	Ground
B43	N/C	A43	PAR
B44	C_BE#1	A44	AD15
B45	AD14	A45	N/C
B46	Ground	A46	AD13
B47	AD12	A47	AD11
B48	AD10	A48	Ground
B49	Ground	A49	AD9
	KEY		KEY
	KEY		KEY
B52	AD8	A52	C_BE#0
B53	AD7	A53	N/C
B54	N/C	A54	AD6
B55	AD5	A55	AD4
B56	AD3	A56	Ground
B57	Ground	A57	
B58	AD1	A58	AD0
B59	V5P0	A59	V5P0
B60	ACK64#	A60	REQ64#
B61	V5P0	A61	V5P0
B62	V5P0	A62	V5P0

J6, J7: IDE Connectors (Sec=40, Pri=44)

P.N.	Description	P.N.	Description
1	RESET#	2	Ground
3	Data 7	4	Data 8
5	Data 6	6	Data 9
7	Data 5	8	Data 10
9	Data 4	10	Data 11
11	Data 3	12	Data 12
13	Data 2	14	Data 13
15	Data 1	16	Data 14
17	Data 0	18	Data 15
19	Ground	20	V5P0
21	DMAREQ	22	Ground
23	IOW#	24	Ground
25	IOR#	26	Ground
27	IOCHRDY	28	Ground
29	DMAACK#	30	Ground
31	IRQ15/14	32	N/C
33	SA1	34	PDIAG#/CSEL
35	SA0	36	SA2
37	HDCCS0#	38	HDCCS1#
39	HDDACTIVE#	40	Ground
41	V3P3	42	V3P3
43	Ground	44	N/C

J8: Dual USB Port Connector

P.N.	Description	P.N.	Description
1	5VP0	5	5VP0
2	USBD0-	6	USBD1-
3	USBD0+	7	USBD1+
4	Ground	8	Ground

J9: Dual USB Header

P.N.	Description	P.N.	Description
1	PWR0	6	D1+
2	PWR1	7	GND0
3	D0-	8	GND1
4	D1-	9	KEY
5	D0+	10	OC#

J10-A: VGA

P.N.	Description	P.N.	Description
1	RV	2	GV
3	BV	4	MON2PU
5	Ground	6	Ground
7	Ground	8	Ground
9	V5P0	10	Ground
11	MONOPU	12	DDCDA
13	HS	14	VS
15	DDCCL		

J10B: Serial Port connector

Pin Number	Signal Description
1	DCD
2	RXD
3	TXD
4	DTR
5	SGND
6	DSR
7	RTS
8	CTS
9	RI
10	N/C (J1 Only)

J11: Serial Port connector

Pin Number	Signal Description
1	DCD
2	RXD
3	TXD
4	DTR
5	SGND
6	DSR
7	RTS
8	CTS
9	RI
10	N/C (J1 Only)

J12: DVO Connector

J13, J14: Ethernet RJ45 (8P8C) Connector

P.N.	Description	P.N.	Description
1	TX+	2	TX-
3	RX+	4	Termplane
5	Termplane	6	RX-
7	Termplane	8	Termplane

J15: DC15V/5A Power Jack Connector

Pin Number	Signal Description
1	V15P0
2	Ground
3	Ground

J16: Reset push button (Momentary)

Pin Number	Signal Description
1	Reset signal
2	Ground

J17: Power output connector to HDD

Pin Number	Signal Description
1	V12P0
2	Ground
3	Ground
4	V5P0

J18: KB/Mouse

P.N.	Description	P.N.	Description
1	KDAT	2	N/C
3	Ground	4	Ground
5	KCLK	6	N/C
7	MDAT	8	N/C
9	Ground	10	V5P0
11	MCLK	12	N/C
13	Ground	14	Ground
15	Ground	16	Ground
17	Ground		

J19-A: MIC

J19-B: Line In

J19-C: Headphone Out

J20: CD-ROM Audio

Pin Number	Signal Description
1	Left In
2	Ground In
3	Ground In
4	Right In

J21: Audio Planar

P.N.	Description	P.N.	Description
1	Mic In	2	GND Audio
3	Mic Bias	4	V5VAUD
5	Out Right	6	Ret Right
7	RSVD	8	KEY
9	Out Left	10	Ret Left
11	Amp R+	12	Amp R-
13	Amp L+	14	Amp L-

JUMPER TABLE

JUMPER Ref.	FUNCTION	DEFAULT SETTING
JP1	CLEAR CMOS RAM 1-2 : Normal 2-3 : CLEAR CMOS RAM	1-2 : Normal
JP2	CPU Frequency Strapping IN : Force CPU Frequency to safe mode OUT : Use CPU Frequency strapping in ICH2 Register	OUT : By ICH2 Reg.
JP3	FWH Top Block LOCK IN : TOP BLOCK UNLOCK OUT : TOP BLOCK LOCK	IN : UNLOCK
JP4	Ring Indicator Select 1-2 : RI Disconnected, External 12 V 2-3 : RI Connected	2-3 : RI Connected
JP5	Ring Indicator Select 1-2 : RI Disconnected, External 12 V 2-3 : RI Connected	2-3 : RI Connected

REVISION HISTORY

VERSION	DESCRIPTION
1.0	Rev. B boards built
1.1	Used PSB resistor strapping instead of BSEL

Intel Corporation

5000 W. Chandler Blvd.
Chandler, AZ 85226

Title

REFERENCE TABLES

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